

Features

- Low power consumption
- Low voltage drop
- Low temperature coefficient
- High input voltage (up to 40V)
- Output voltage accuracy: tolerance $\pm 1.5\%$
- Soft start function
- Over current protection
- Over temperature protection
- Package types
3-pin SOT89, 5-pin SOT89/SOT23, 8-pin SOP-EP

Applications

- Industrial/Automotive Application
- Power Meter, Water Meter, Smart Meter
- Portable/Battery-Powered Equipment

General Description

The HT75Hxx series is a set of low power consumption high voltage regulator implemented in a BCD technology, which ensures low voltage drop and low quiescent current. They allow input voltages as high as 40V. They are available with several fixed output voltages ranging from 2.1V to 5.0V.

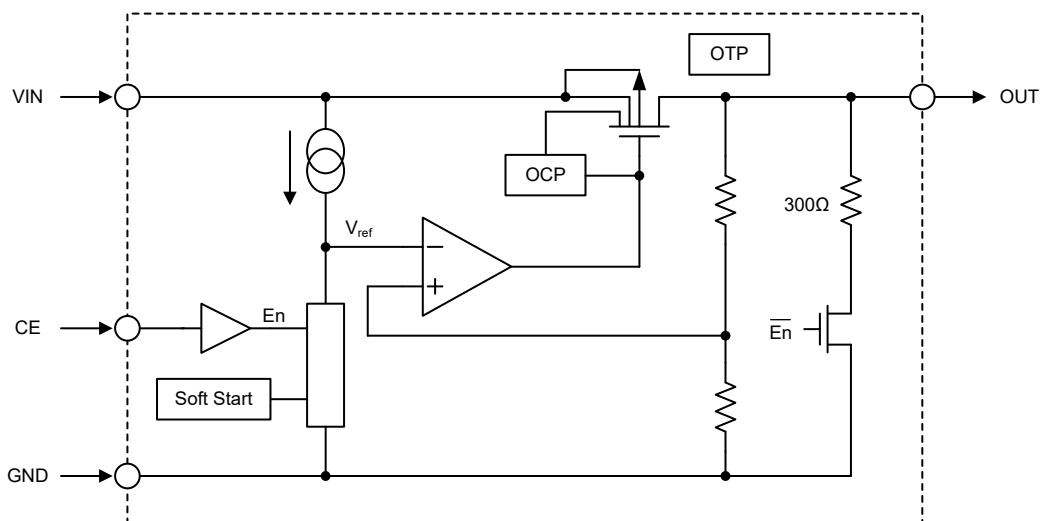
The soft start function controls the output slew rate to prevent the overshooting phenomenon when power on. The enable pin, CE, accepts CMOS level as logic input. When CE goes low, a fast discharging path pulls output voltage low a via 300 Ω resistor. The internally output over current protection prevents the HT75Hxx from being burned even if the output node shorts to ground. The over temperature protection ensures that the junction temperature will not exceed 150°C. The soft start function inhibits the output overshooting when power on.

Selection Table

Part No.	Output Voltage	Package	Marking
HT75H21	2.1V	SOT89 SOT89-5 SOT23-5 8SOP-EP	HT75Hxx (for SOT89, SOT89-5, 8SOP-EP) 5Hxx (for SOT23-5)
HT75H23	2.3V		
HT75H25	2.5V		
HT75H27	2.7V		
HT75H30	3.0V		
HT75H33	3.3V		
HT75H36	3.6V		
HT75H40	4.0V		
HT75H44	4.4V		
HT75H50	5.0V		

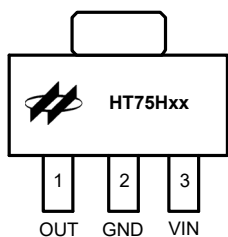
Note: “xx” stands for output voltages.

Block Diagram

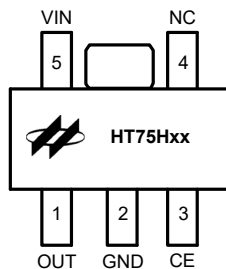


Pin Assignment

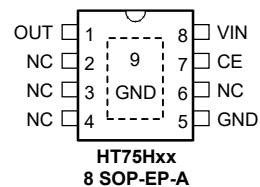
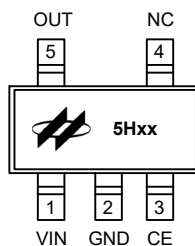
SOT89



SOT89-5



SOT23-5



Pin Descriptions

Pin No.				Pin Name	Pin Description
SOT89	SOT89-5	SOT23-5	8SOP-EP		
3	5	1	8	VIN	Input pin
2	2	2	5, 9	GND	Ground pin
1	1	5	1	OUT	Output pin
—	3	3	7	CE	Chip enable pin, high enable
—	4	4	2, 3, 4, 6	NC	No connection

Absolute Maximum Ratings

Parameter		Value	Unit
V_{IN}		-0.3 to +48	V
V_{CE}		-0.3 to ($V_{IN}+0.3$)	V
Operating Temperature Range, T_a		-40 to +85	°C
Maximum Junction Temperature, $T_{J(MAX)}$		+150	°C
Storage Temperature Range		-65 to +165	°C
ESD Susceptibility	Human Body Model	±5000	V
	Machine Model	±400	V
Junction-to-Ambient Thermal Resistance, θ_{JA}	SOT89	200	°C/W
	SOT89-5	200	°C/W
	SOT23-5	500	°C/W
	8SOP-EP	140	°C/W
Power Dissipation, P_D	SOT89	0.625	W
	SOT89-5	0.625	W
	SOT23-5	0.25	W
	8SOP-EP	0.89	W

Note: P_D is measured at $T_a=25^{\circ}\text{C}$.

Recommended Operating Range

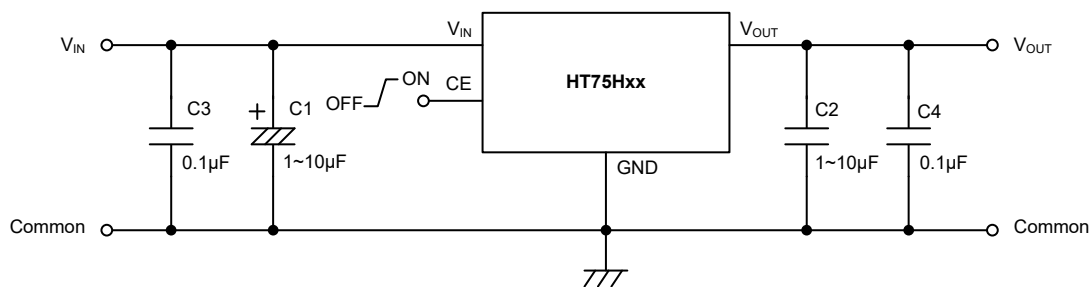
Parameter	Value	Unit
V_{IN}	($V_{OUT}+2$) to 40	V
V_{CE}	0 to V_{IN}	V

Electrical Characteristics

$V_{IN}=V_{OUT}+2V$, $V_{CE}=V_{IN}$, $T_a=25^{\circ}C$ and $C_{IN}=C_{OUT}=1\mu F$, unless otherwise specified

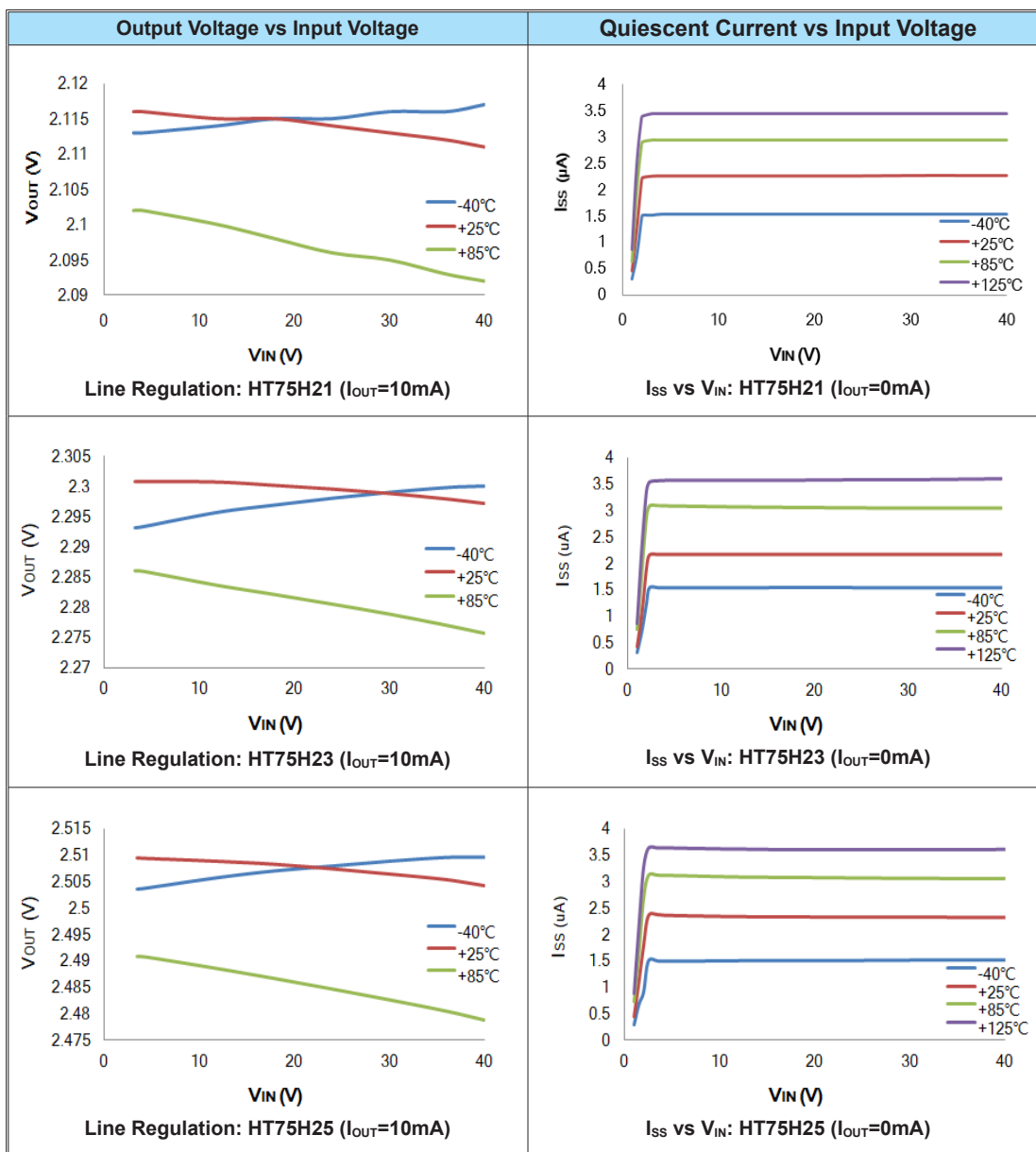
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{IN}	Input Voltage	—	—	—	40	V
V_{OUT}	Output Voltage Range	—	2.1	—	5.0	V
V_O	Output Voltage Accuracy	$I_{OUT}=10mA$	-1.5	—	1.5	%
I_{OUT}	Output Current	$V_{OUT}=2.1V$ to $3.0V$	100	—	—	mA
		$V_{OUT}=3.3V$ to $5.0V$	150	—	—	
ΔV_{OUT}	Load Regulation	$1mA \leq I_{OUT} \leq 50mA$	—	15	45	mV
V_{DIF}	Dropout Voltage	$I_{OUT}=1mA$, V_{OUT} Change=2% (Note)	—	10	30	mV
I_{SS}	Quiescent Current	$I_{OUT}=0mA$	—	2.5	4.0	μA
		$V_{CE}=2.2V$, $V_{IN}=40V$, $I_{OUT}=0mA$	—	3.0	5.0	
I_{SHD}	Shutdown Current	$V_{CE}=0V$	—	0.1	1.0	μA
$\frac{\Delta V_{OUT}}{\Delta V_{IN} \times \Delta V_{OUT}}$	Line Regulation	$(V_{OUT}+1V) \leq V_{IN} \leq 40V$, $I_{OUT}=1mA$	—	0.1	0.2	%/V
$\frac{\Delta V_{OUT}}{\Delta T_a \times \Delta V_{OUT}}$	Temperature Coefficient	$I_{OUT}=10mA$, $-40^{\circ}C < T_a < 85^{\circ}C$	—	± 100	—	ppm/ $^{\circ}C$
I_{OCP1}	OCP1 Current Threshold	$V_{IN}=24V$	—	250	—	mA
I_{OCP2}	OCP2 Current Threshold	$V_{IN}=24V$, force $V_{OUT}=0V$	—	150	—	mA
V_{OCP_TH}	OCP1/OCP2 Current Threshold	Observe at V_{OUT} terminal	—	0.7	—	V
T_{SHD}	Shutdown Temperature	—	—	150	—	$^{\circ}C$
T_{REC}	Recovery Temperature	—	—	120	—	$^{\circ}C$
V_{IH}	Enable High Threshold	CE pin, $(V_{OUT}+1V) \leq V_{IN} \leq 40V$	2	—	—	V
V_{IL}	Enable Low Threshold	CE pin, $(V_{OUT}+1V) \leq V_{IN} \leq 40V$	—	—	0.6	V
R_{DIS}	Discharge Resistor	$V_{IN}=24V$, $CE=0V$, measure at V_{OUT}	—	300	—	Ω
PSRR	Power Supply Rejection Ratio	$V_{IN}=24V$, $V_{OUT}=5V$, $I_{OUT}=10mA$, $f=1kHz$	—	60	—	dB
Noise	Output Voltage Noise	$V_{OUT}=5V$, $I_{OUT}=10mA$, $BW=10Hz \sim 100kHz$	—	75	—	μV_{RMS}

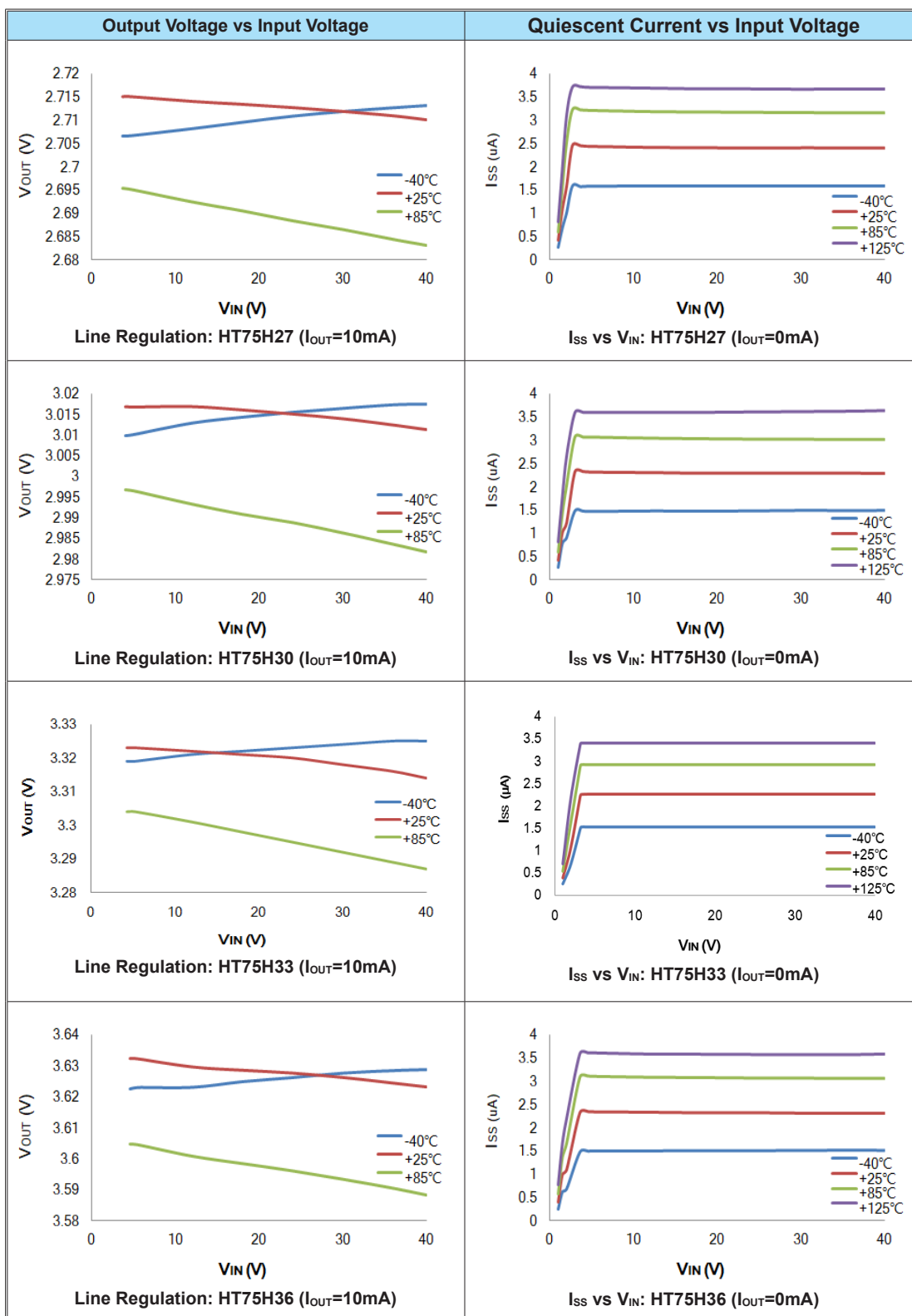
Note: Dropout voltage is defined as the input voltage minus the output voltage that produces a 2% change in the output voltage from the value at $V_{IN}=V_{OUT}+2V$ with a fixed load.

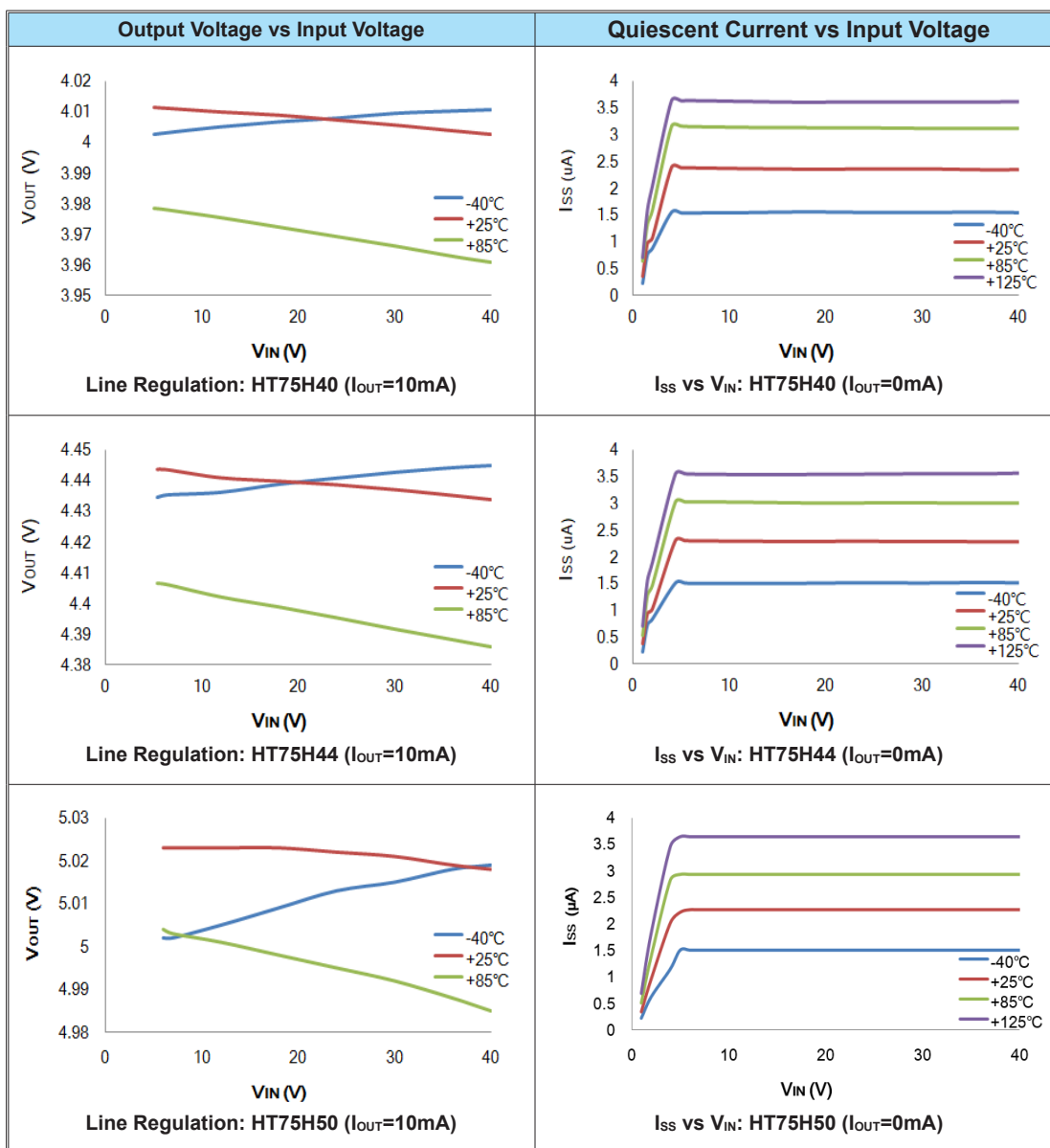


Typical Performance Characteristic

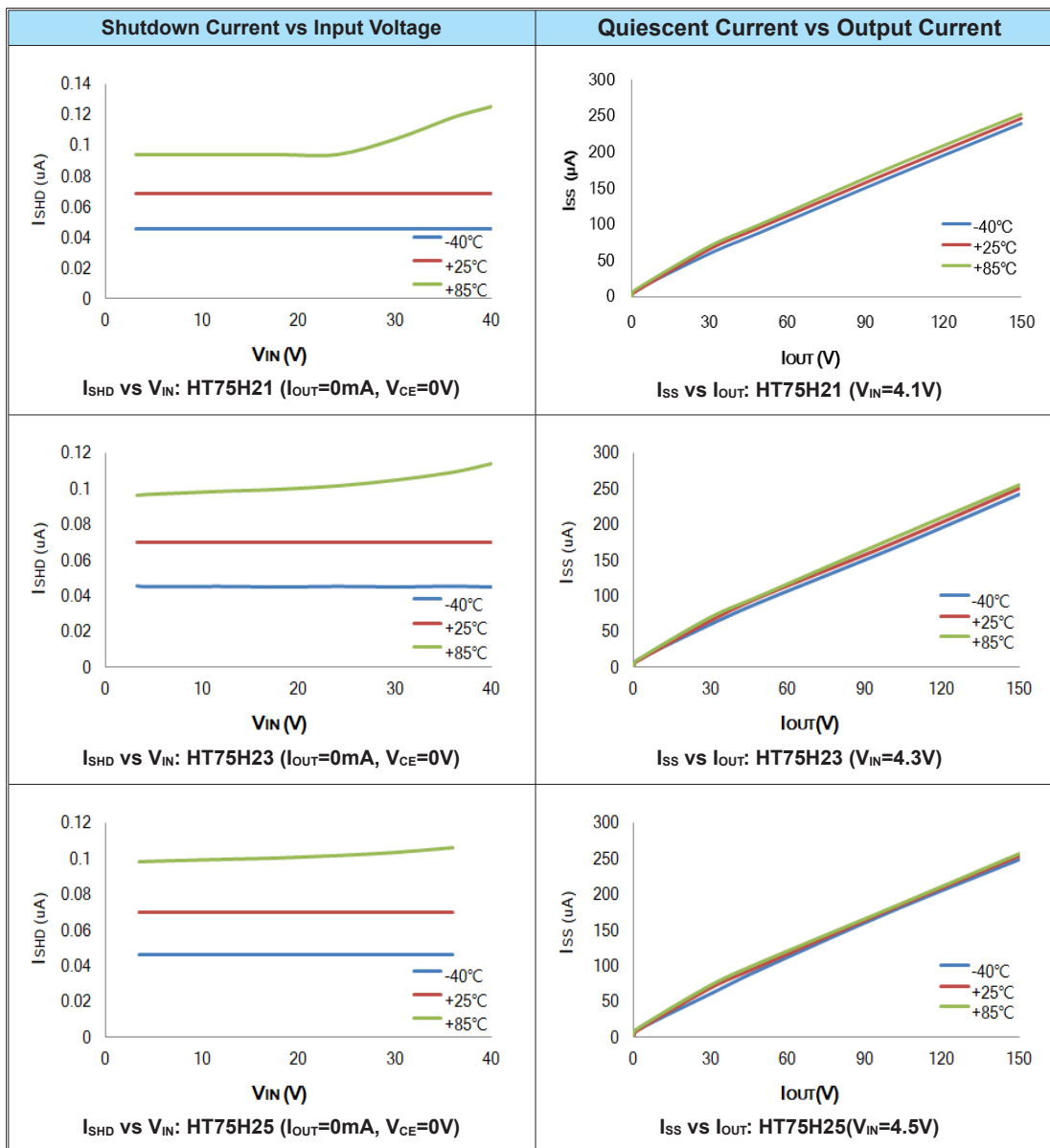
Test Condition: $V_{IN}=V_{OUT}+2V$, $V_{CE}=V_{IN}$, $I_{OUT}=10mA$, $C_{IN}=1\mu F$, $C_{OUT}=1\mu F$ and $T_a=25^{\circ}C$, unless otherwise noted.

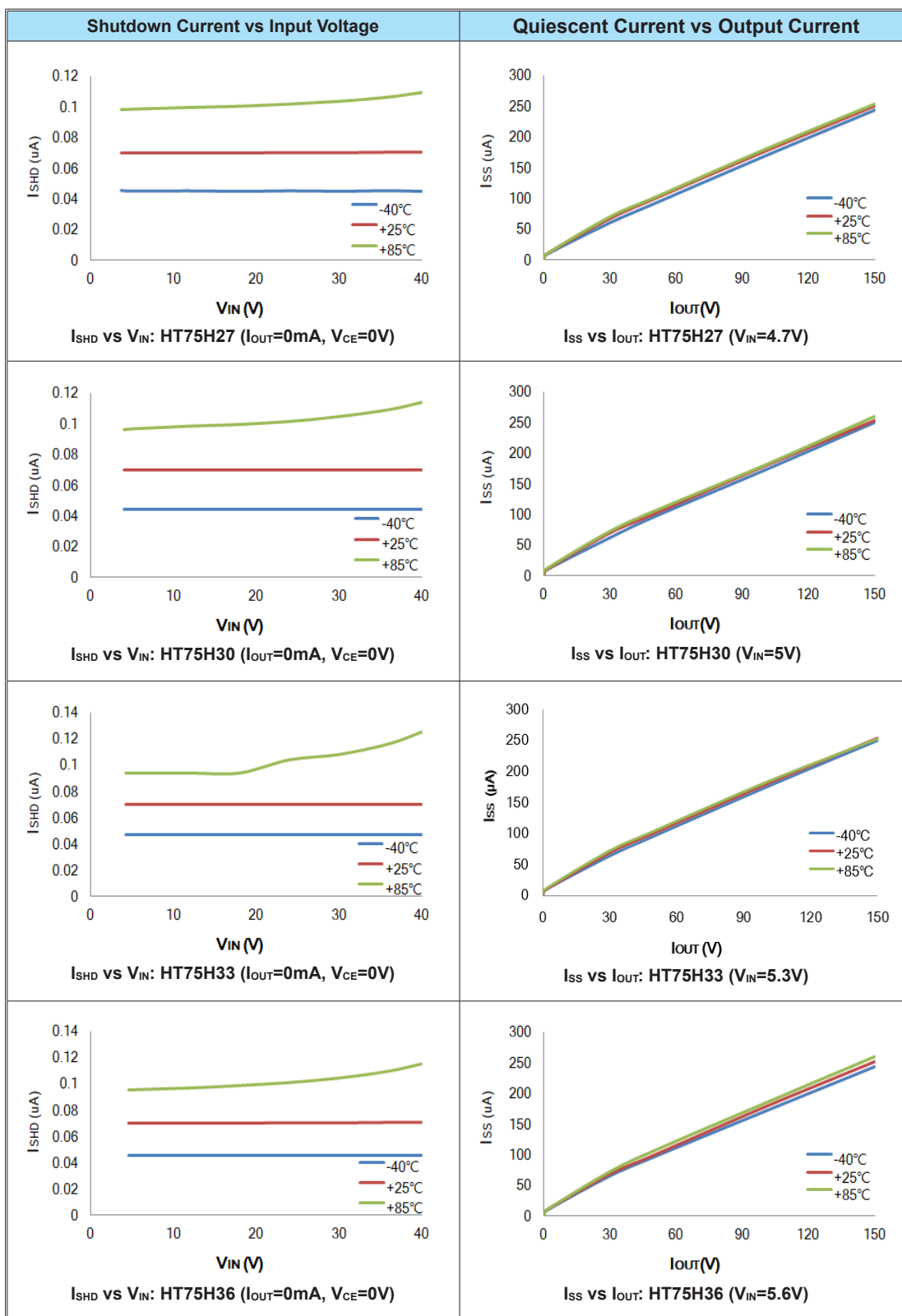


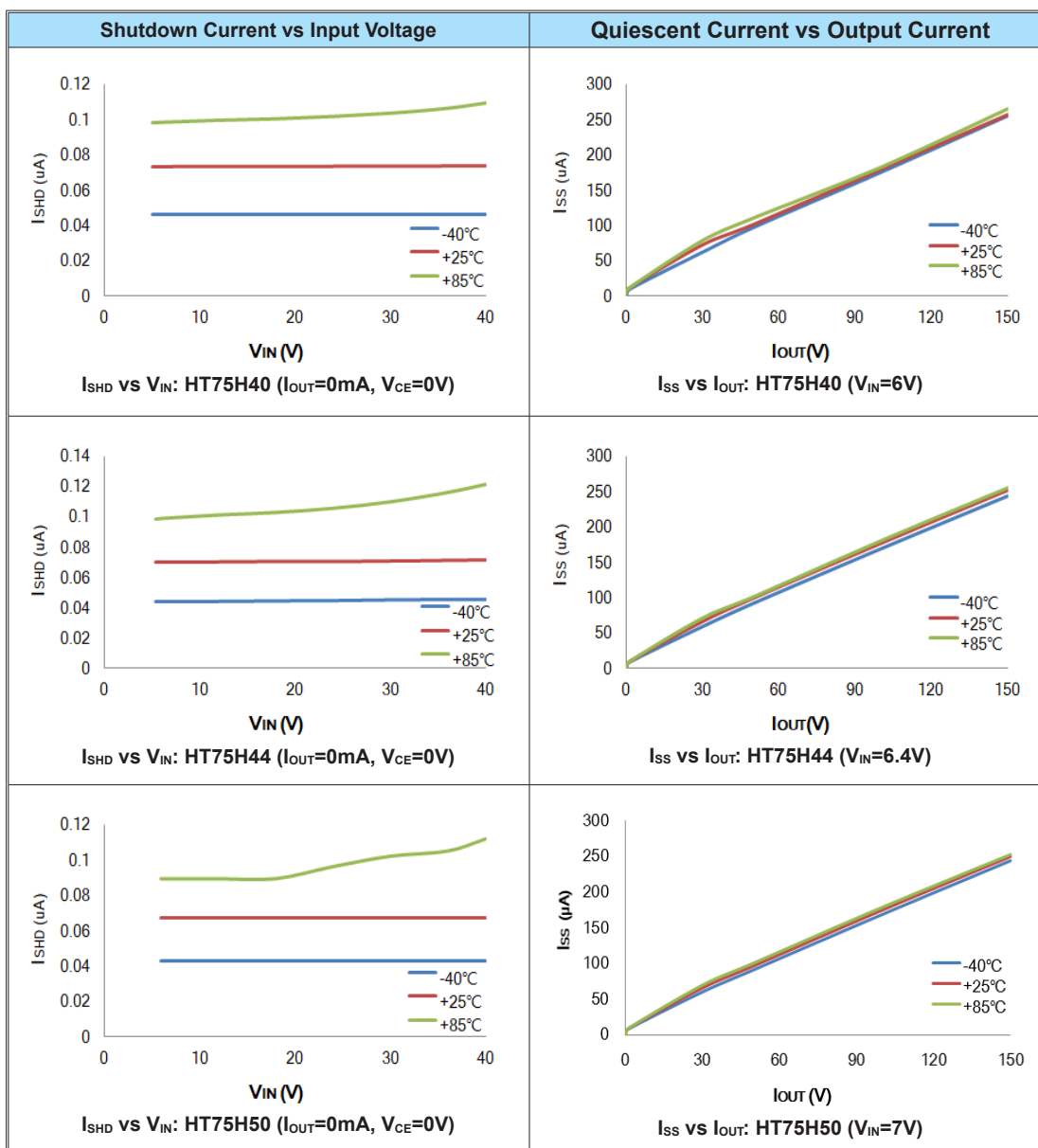




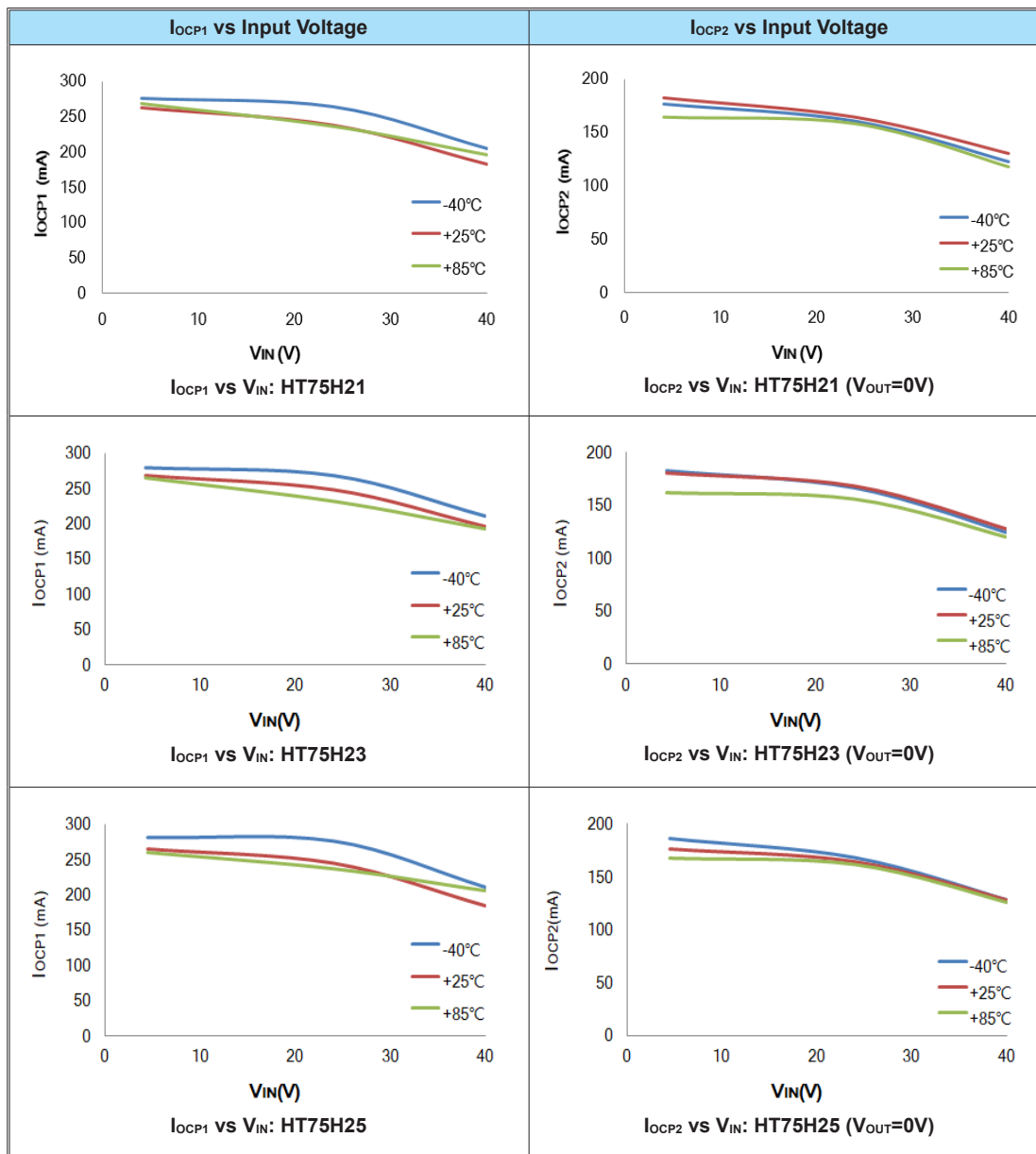
Test Condition: $V_{IN}=V_{OUT}+2V$, $V_{CE}=V_{IN}$, $I_{OUT}=10mA$, $C_{IN}=1\mu F$, $C_{OUT}=1\mu F$ and $T_a=25^\circ C$, unless otherwise noted.

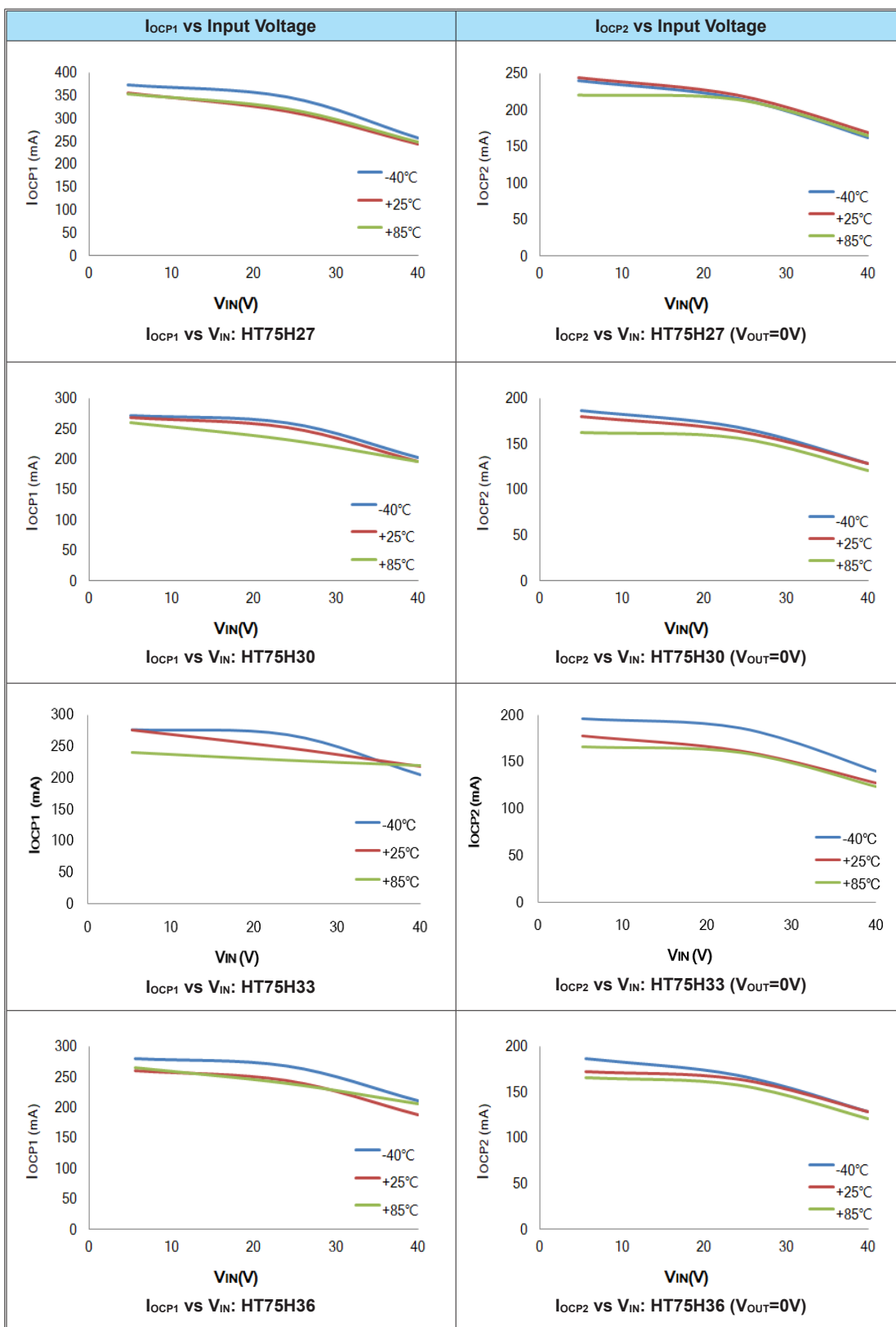


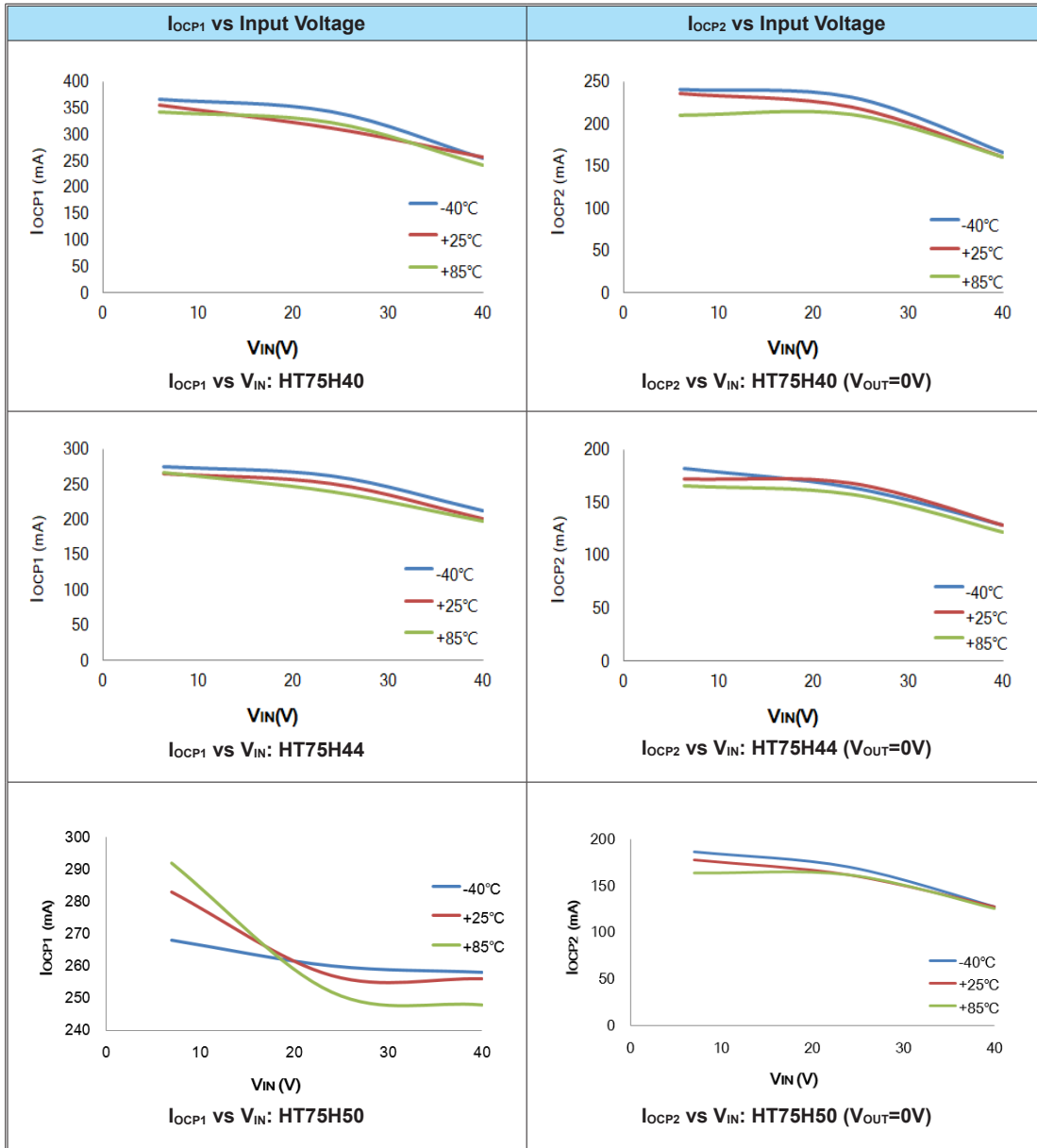




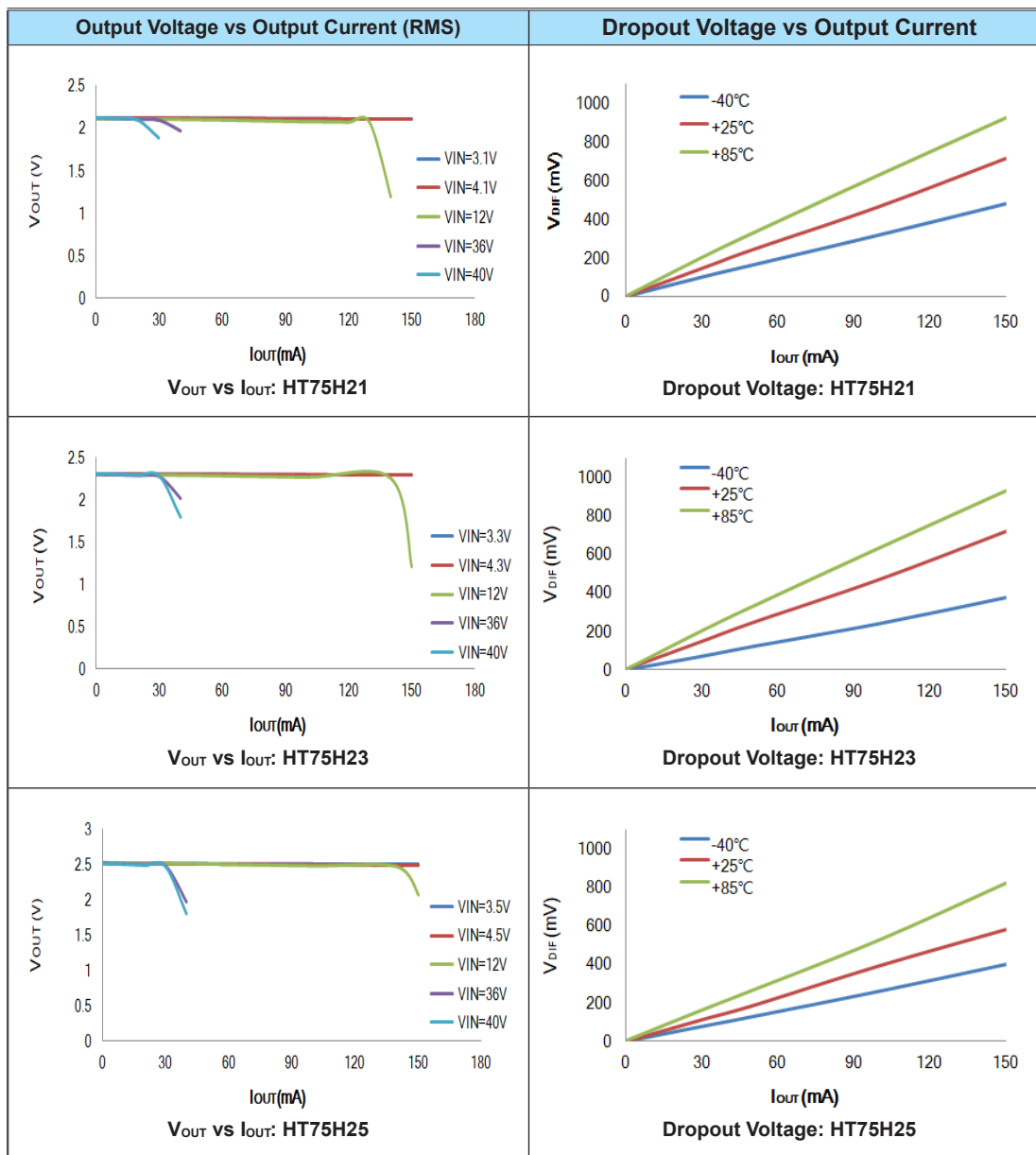
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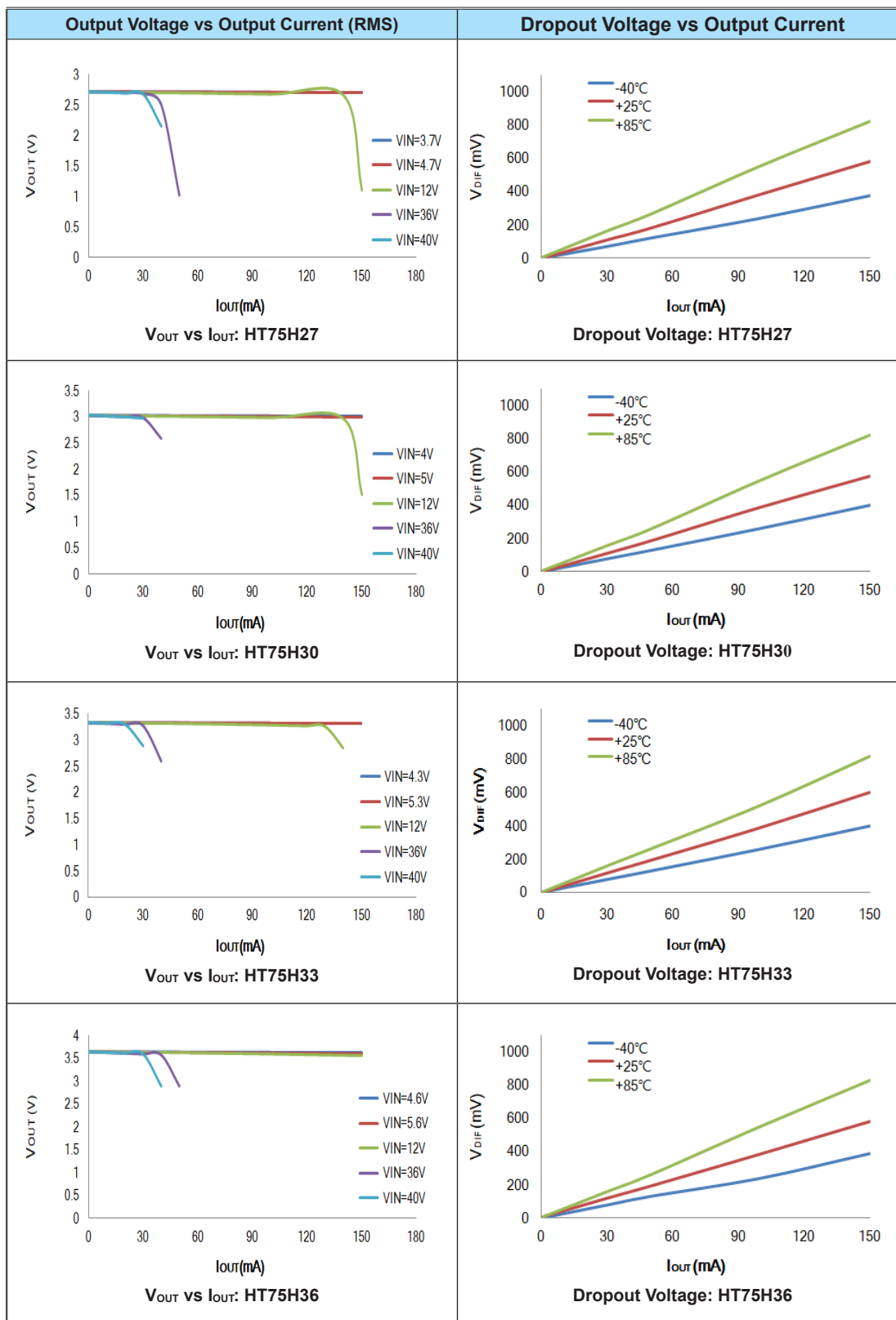


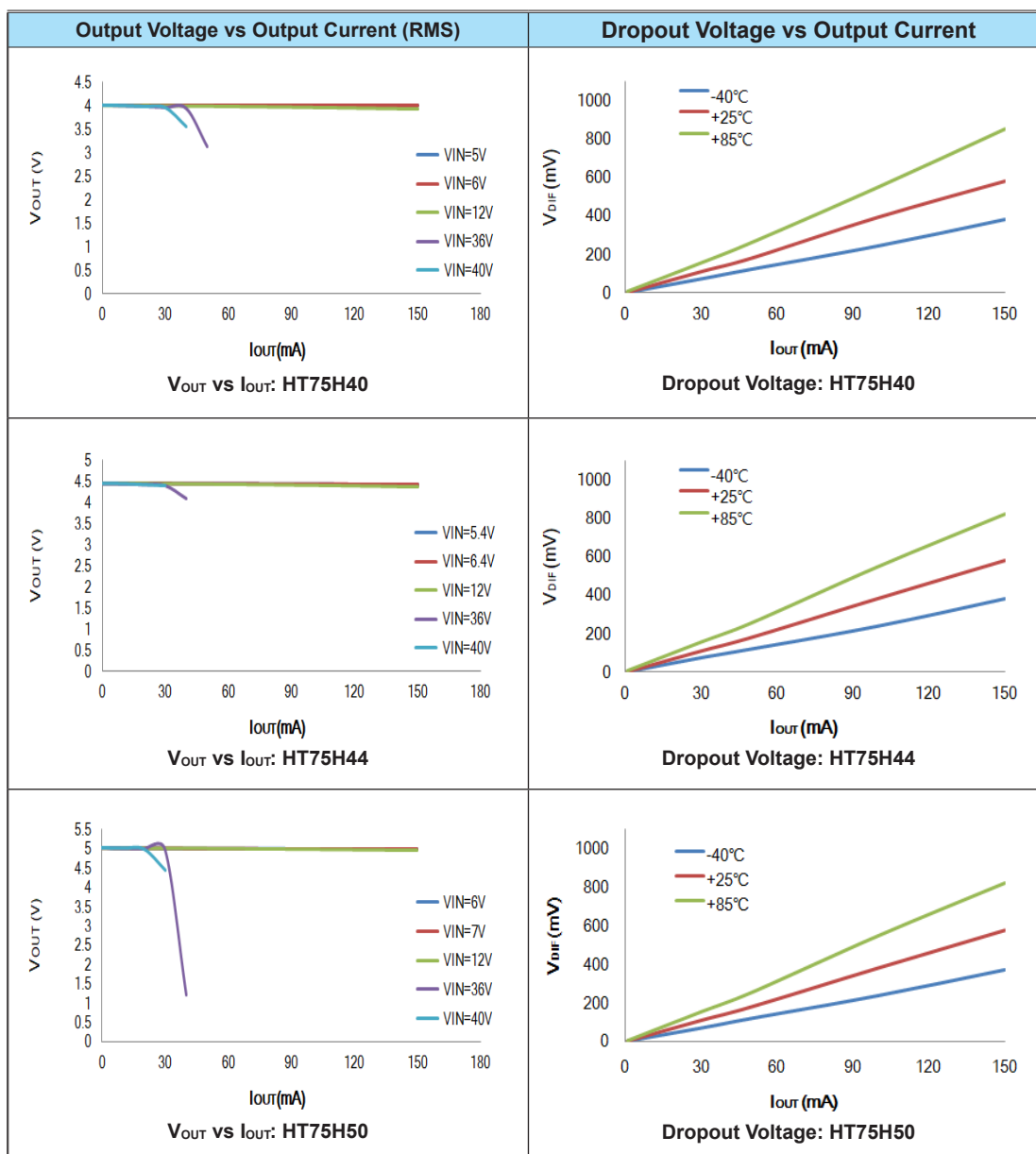




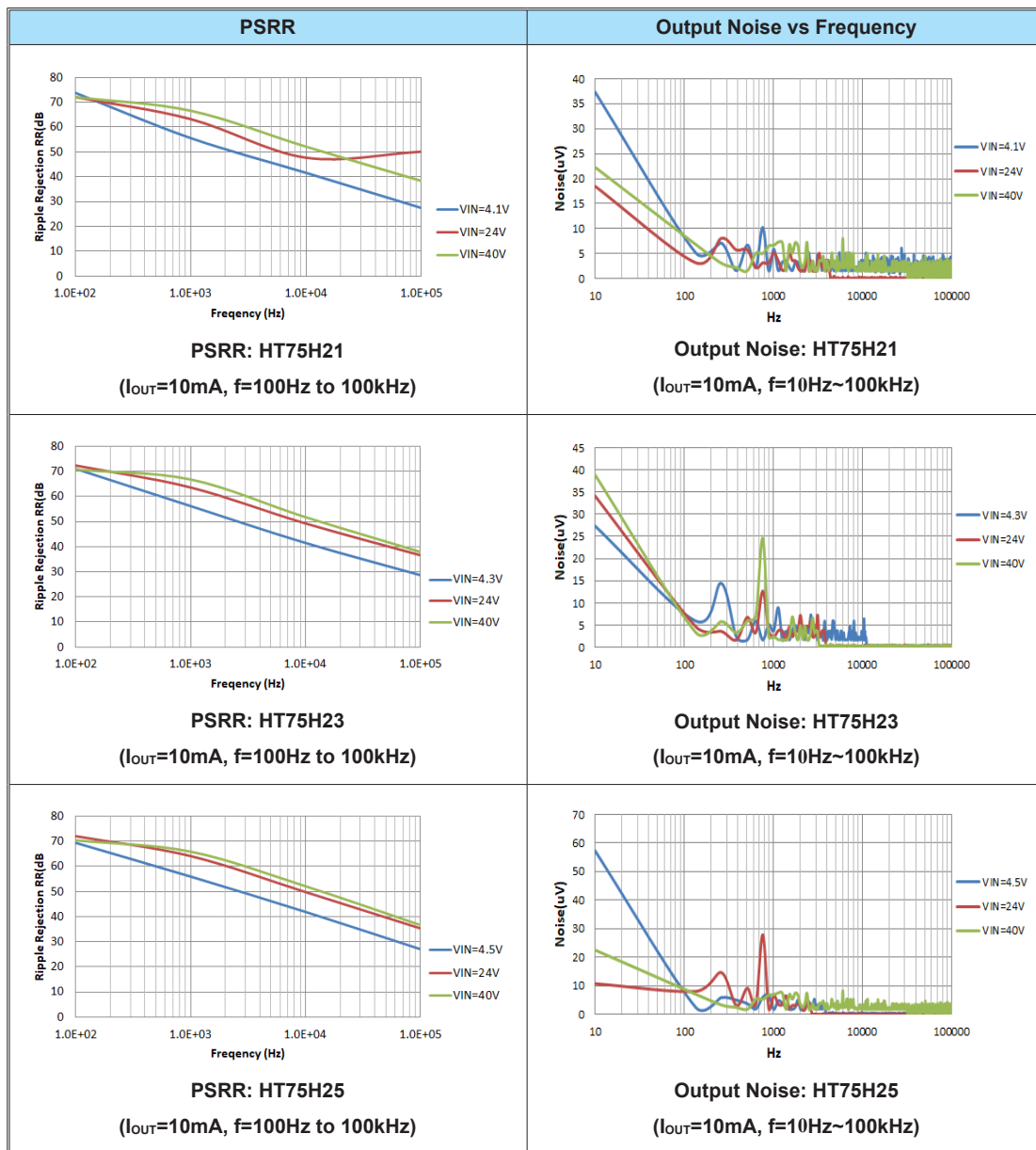
Test Condition: $V_{IN}=V_{OUT}+2V$, $V_{CE}=V_{IN}$, $I_{OUT}=10mA$, $C_{IN}=1\mu F$, $C_{OUT}=1\mu F$ and $T_a=25^\circ C$, unless otherwise noted.

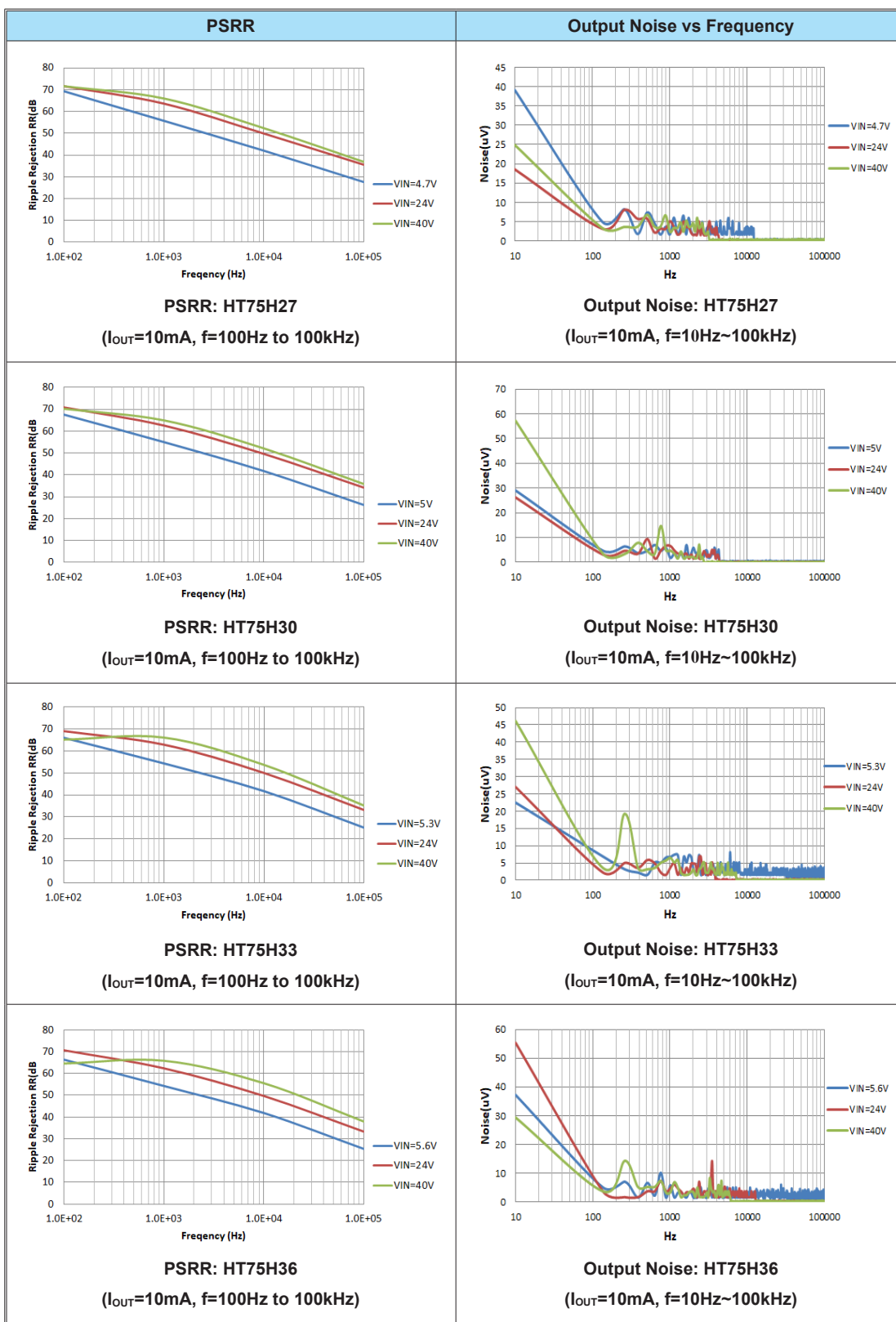


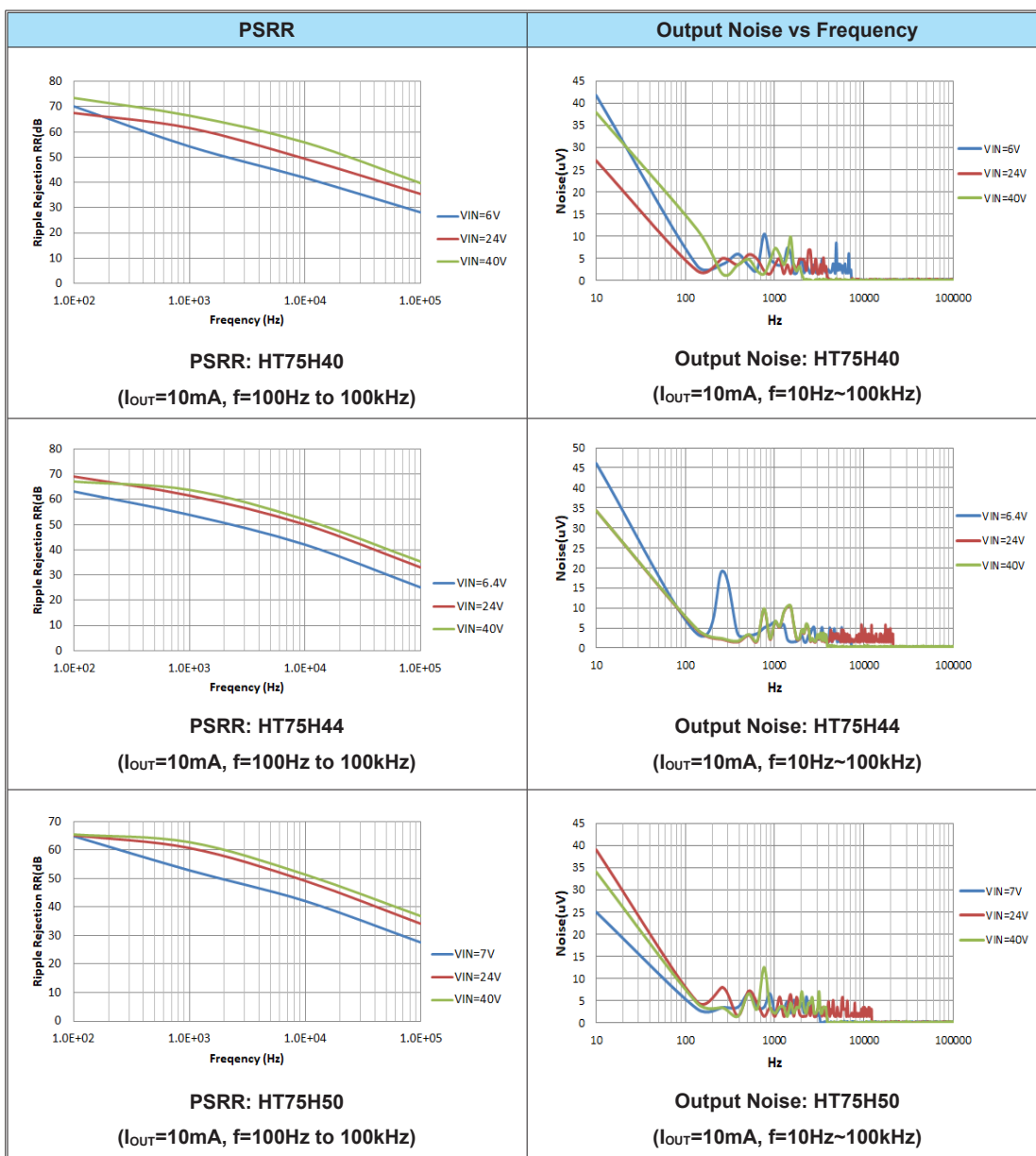




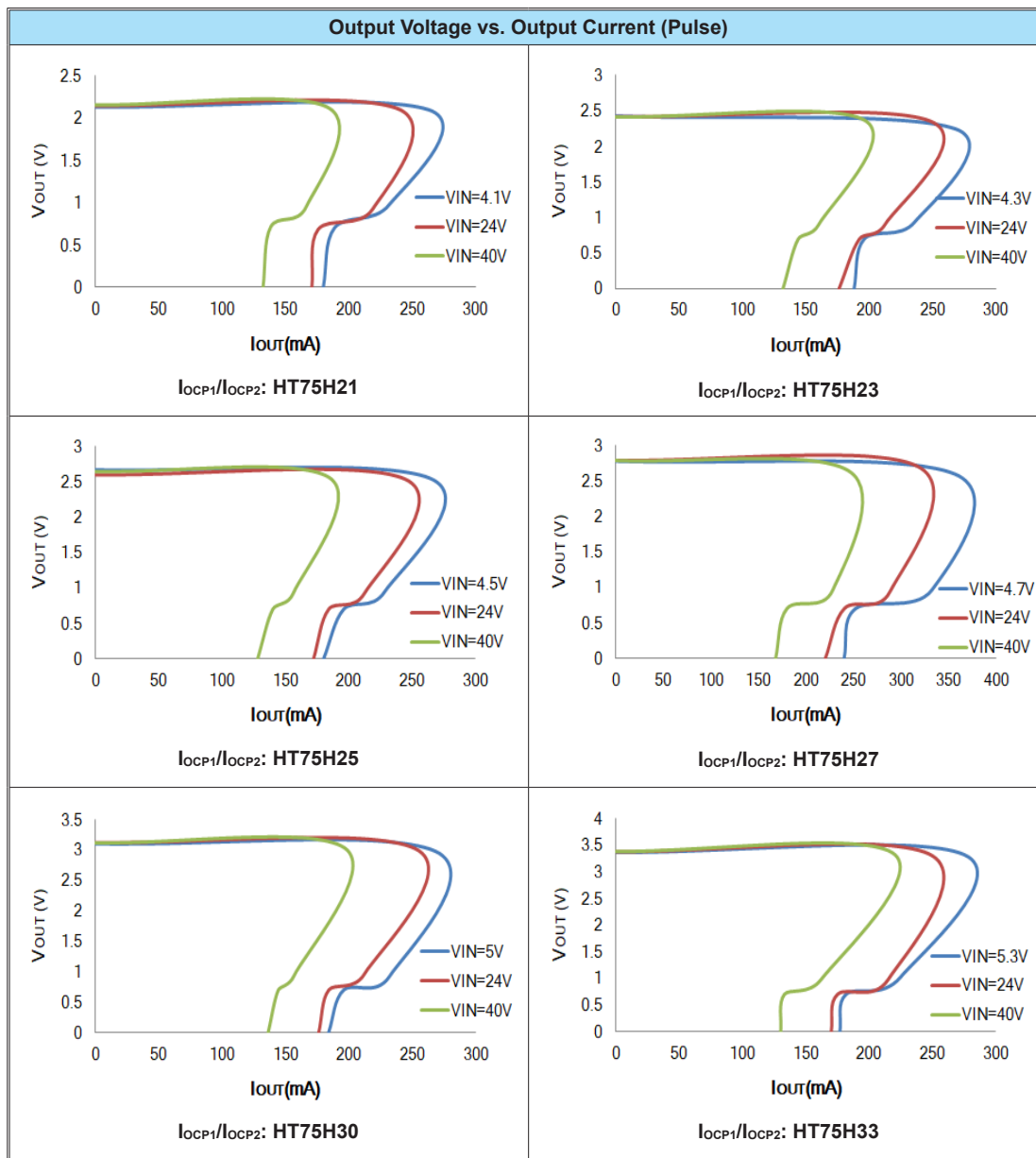
Test Condition: $V_{IN}=V_{OUT}+2V$, $V_{CE}=V_{IN}$, $I_{OUT}=10mA$, $C_{IN}=1\mu F$, $C_{OUT}=1\mu F$ and $T_a=25^\circ C$, unless otherwise noted.

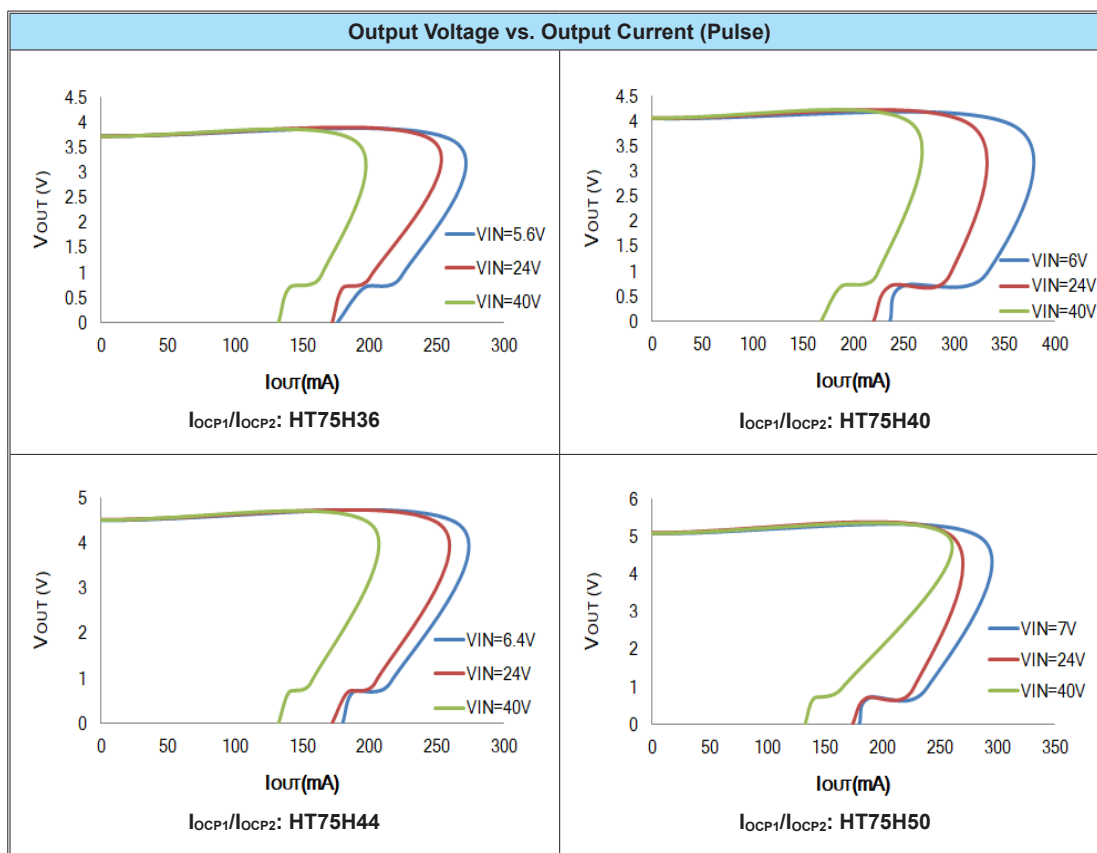




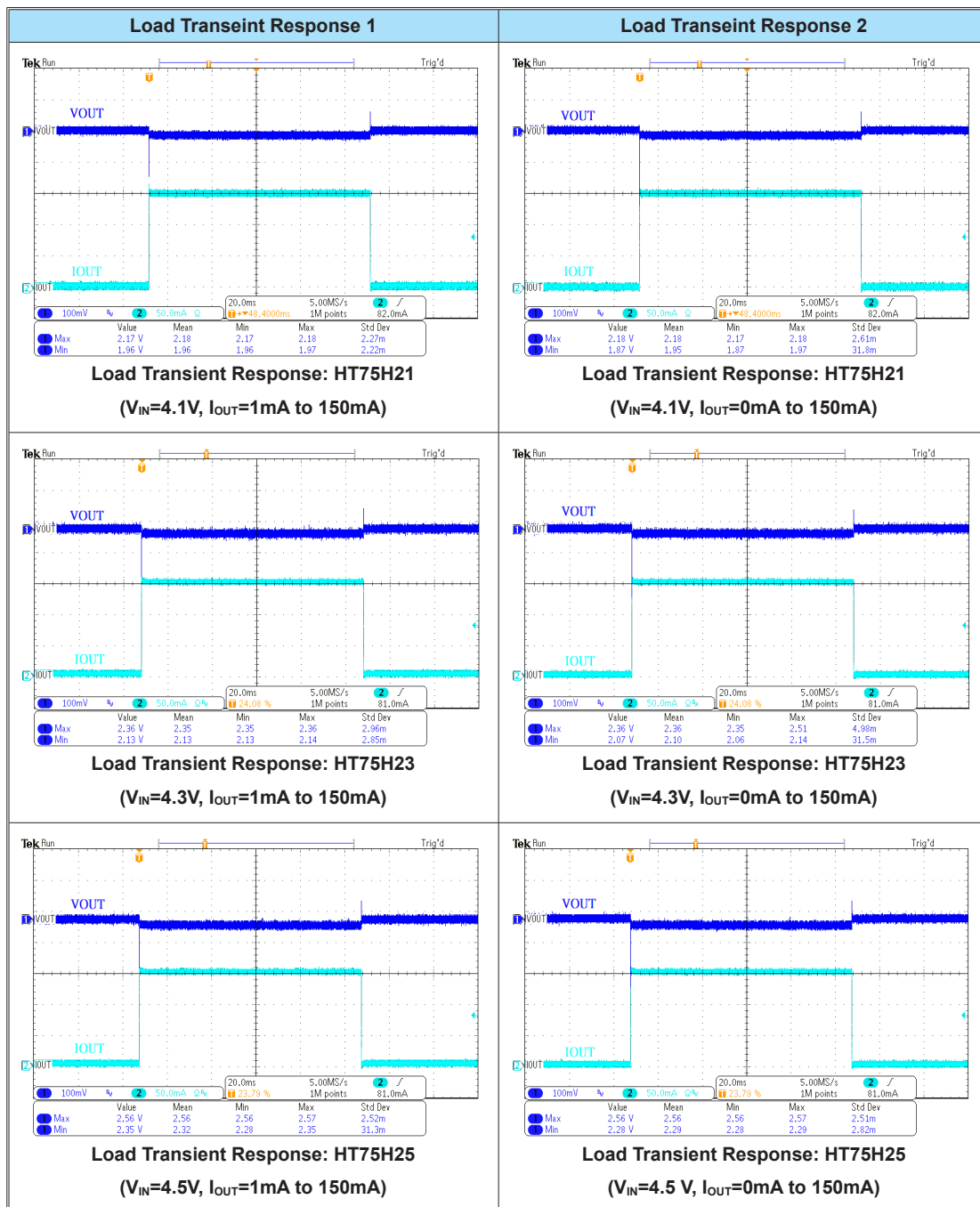


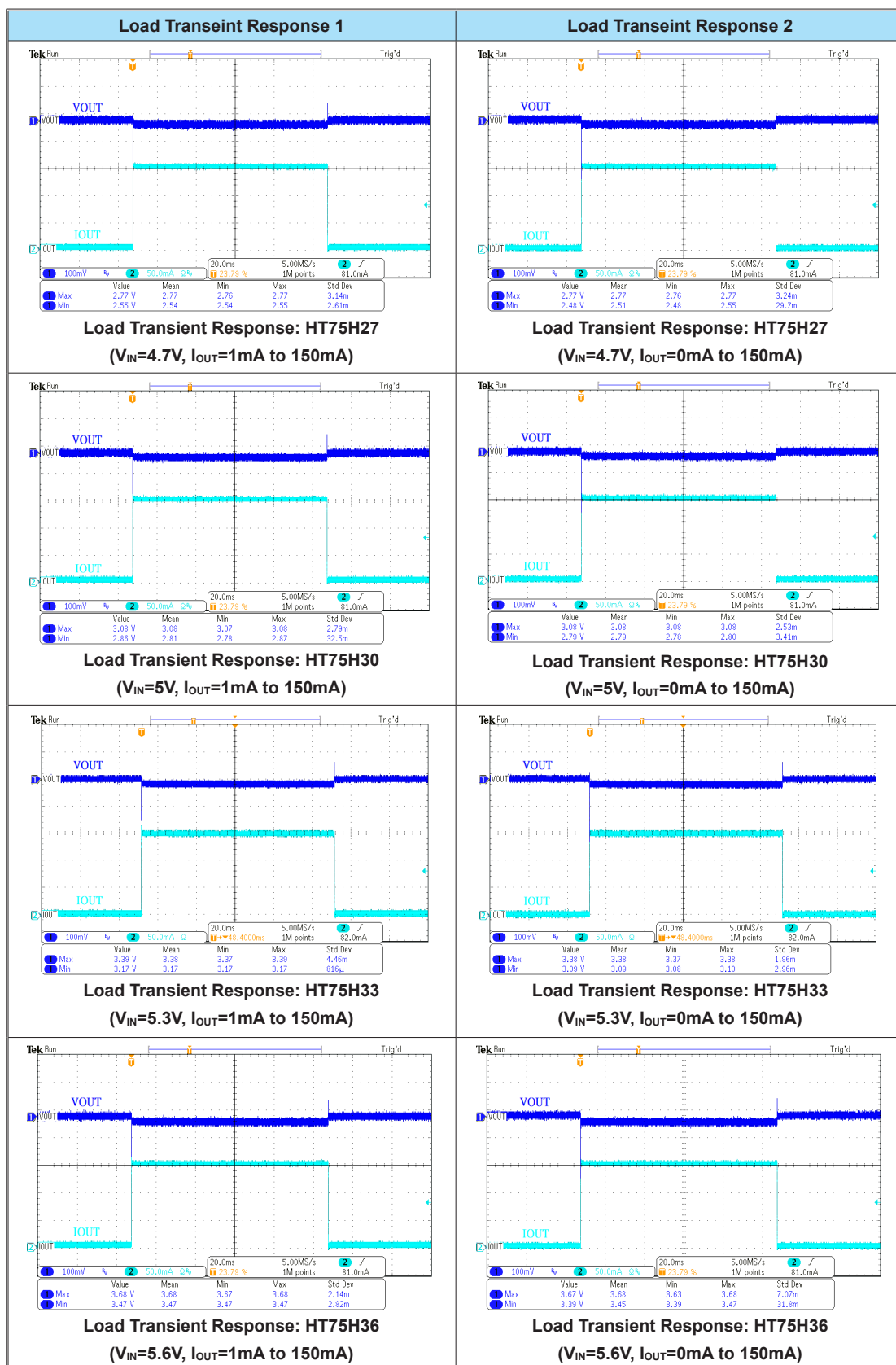
Test Condition: $V_{IN}=V_{OUT}+2V$, $V_{CE}=V_{IN}$, $I_{OUT}=10mA$, $C_{IN}=1\mu F$, $C_{OUT}=1\mu F$ and $T_a=25^{\circ}C$, unless otherwise noted.

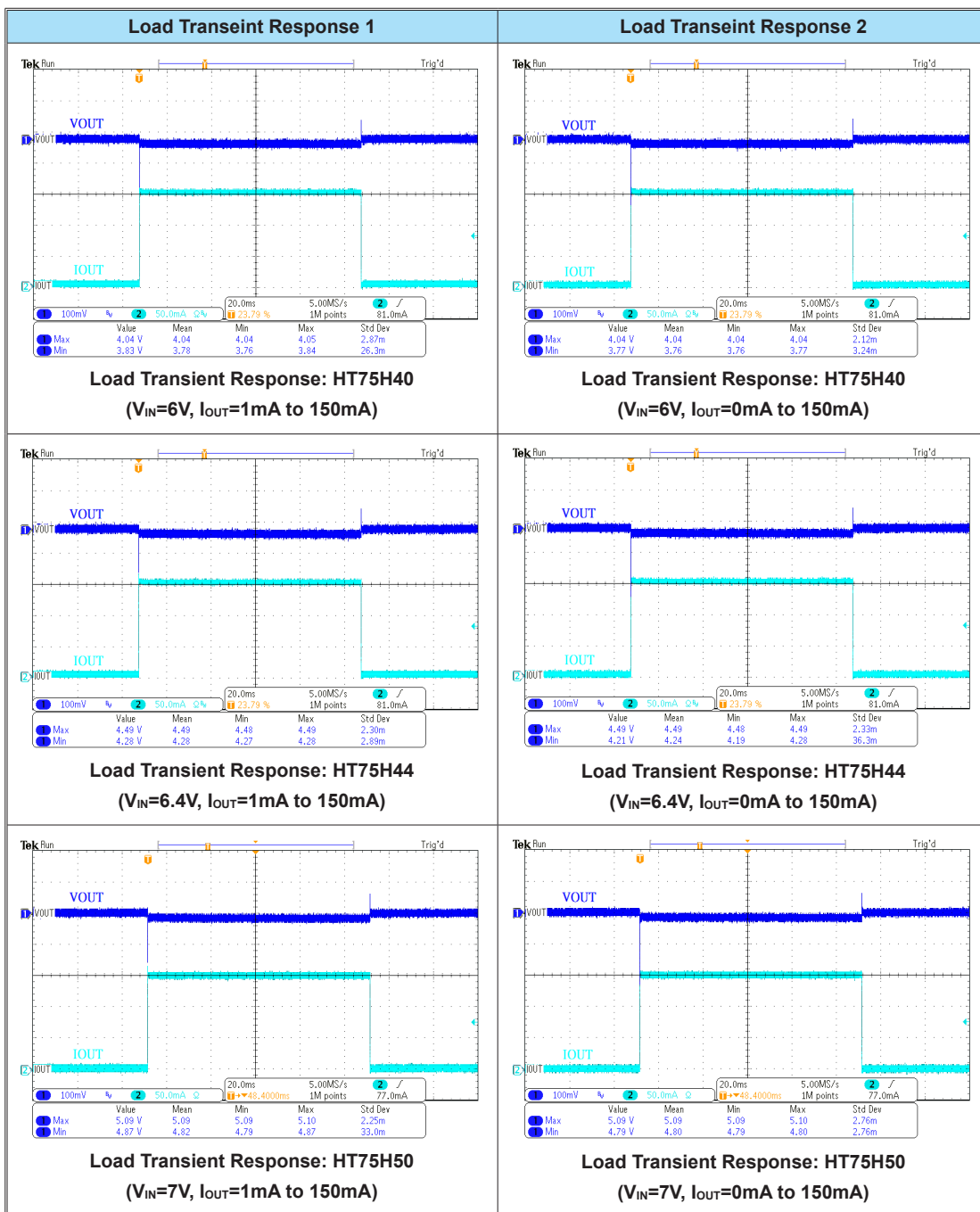




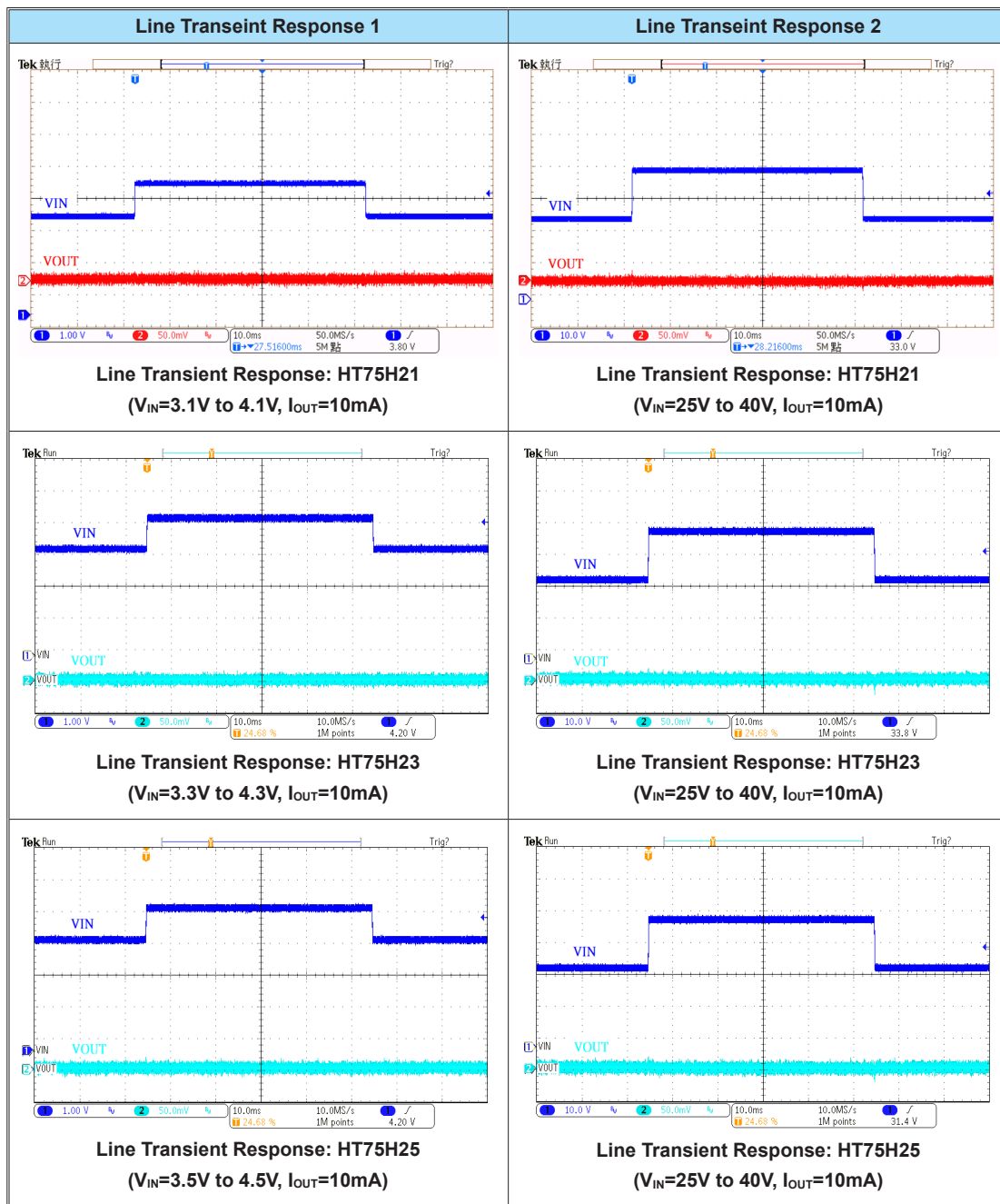
Test Condition: $V_{IN}=V_{OUT}+2V$, $V_{CE}=V_{IN}$, $I_{OUT}=10mA$, $C_{IN}=1\mu F$, $C_{OUT}=1\mu F$ and $T_a=25^{\circ}C$, unless otherwise noted.

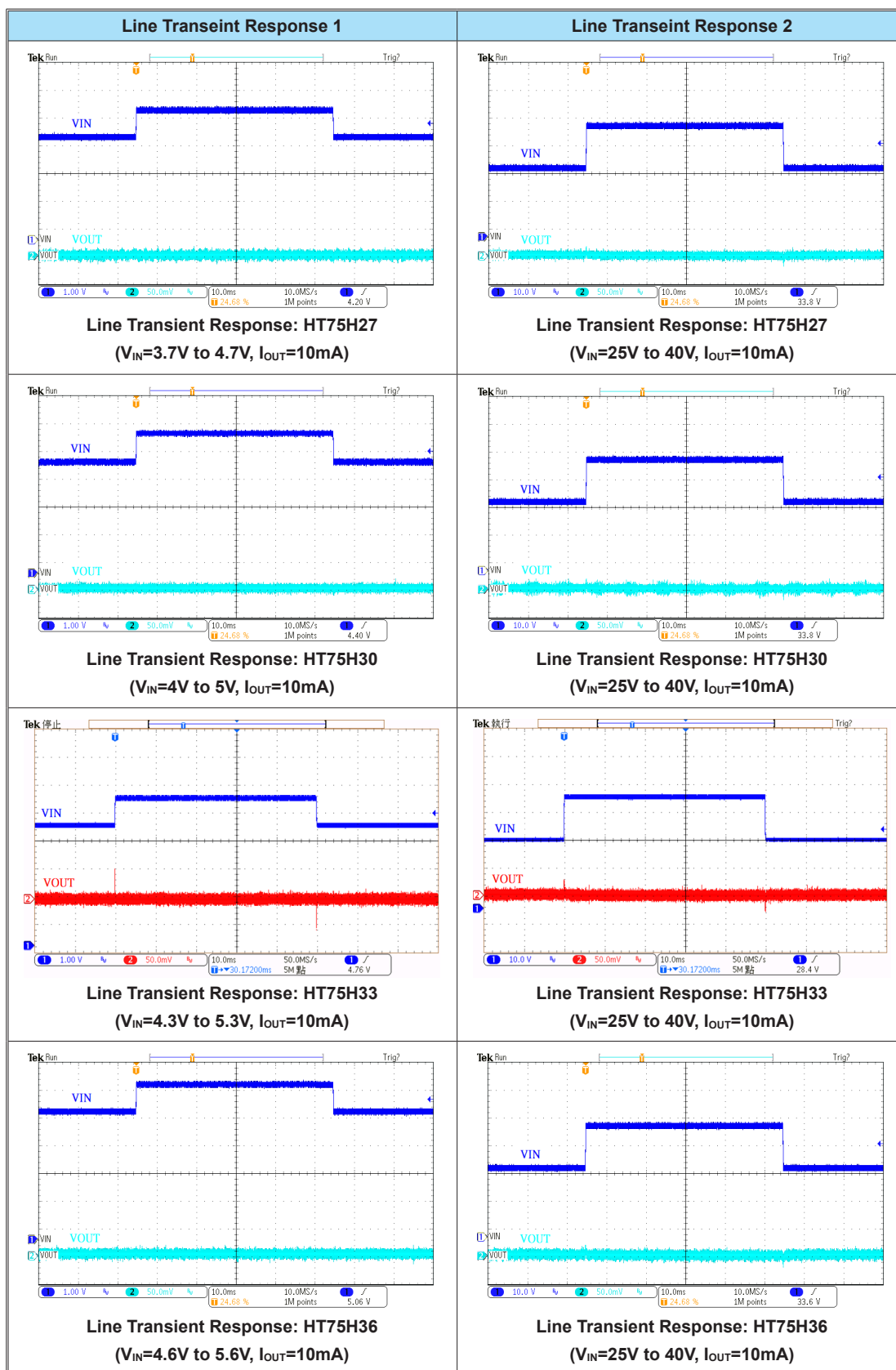


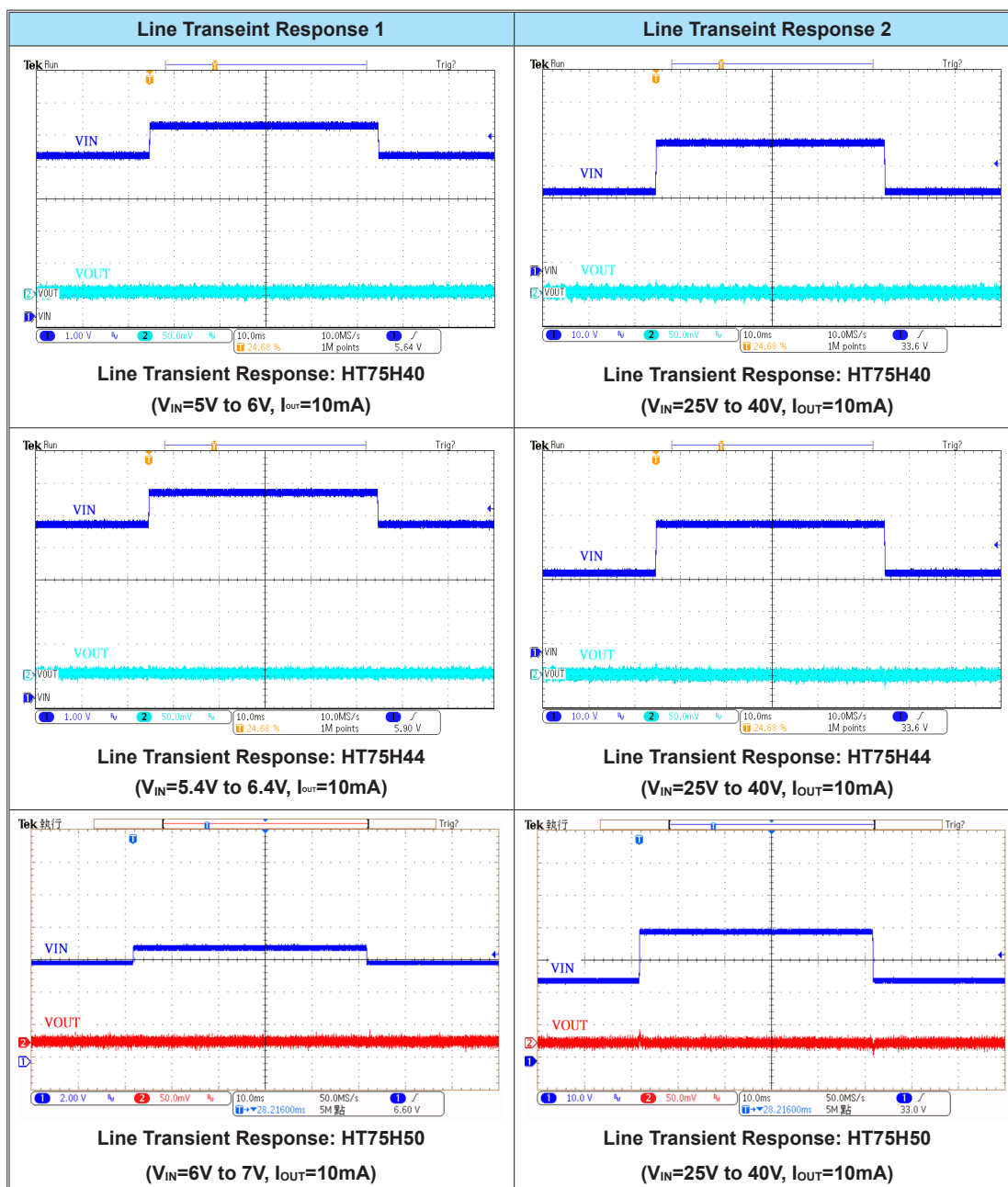




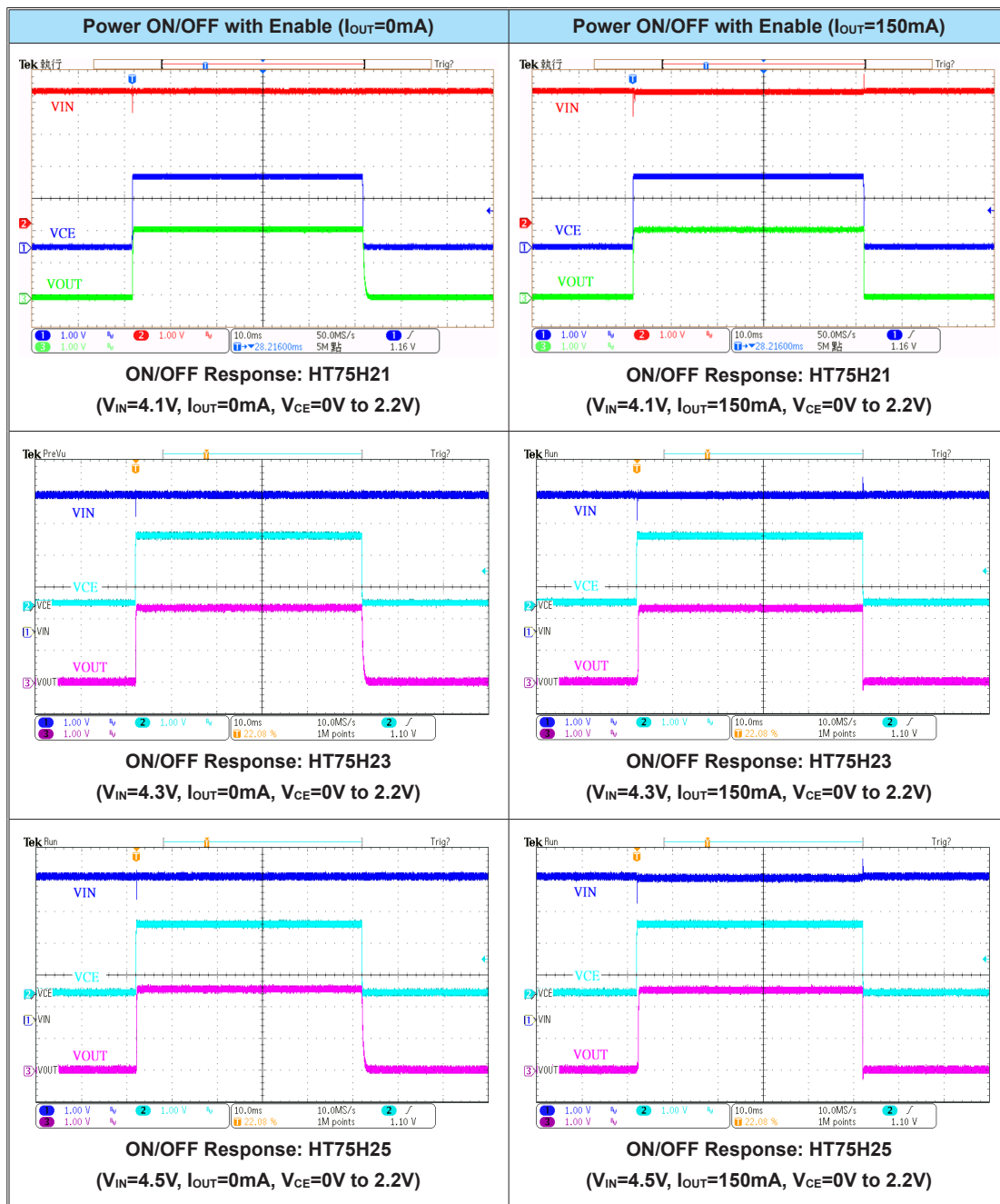
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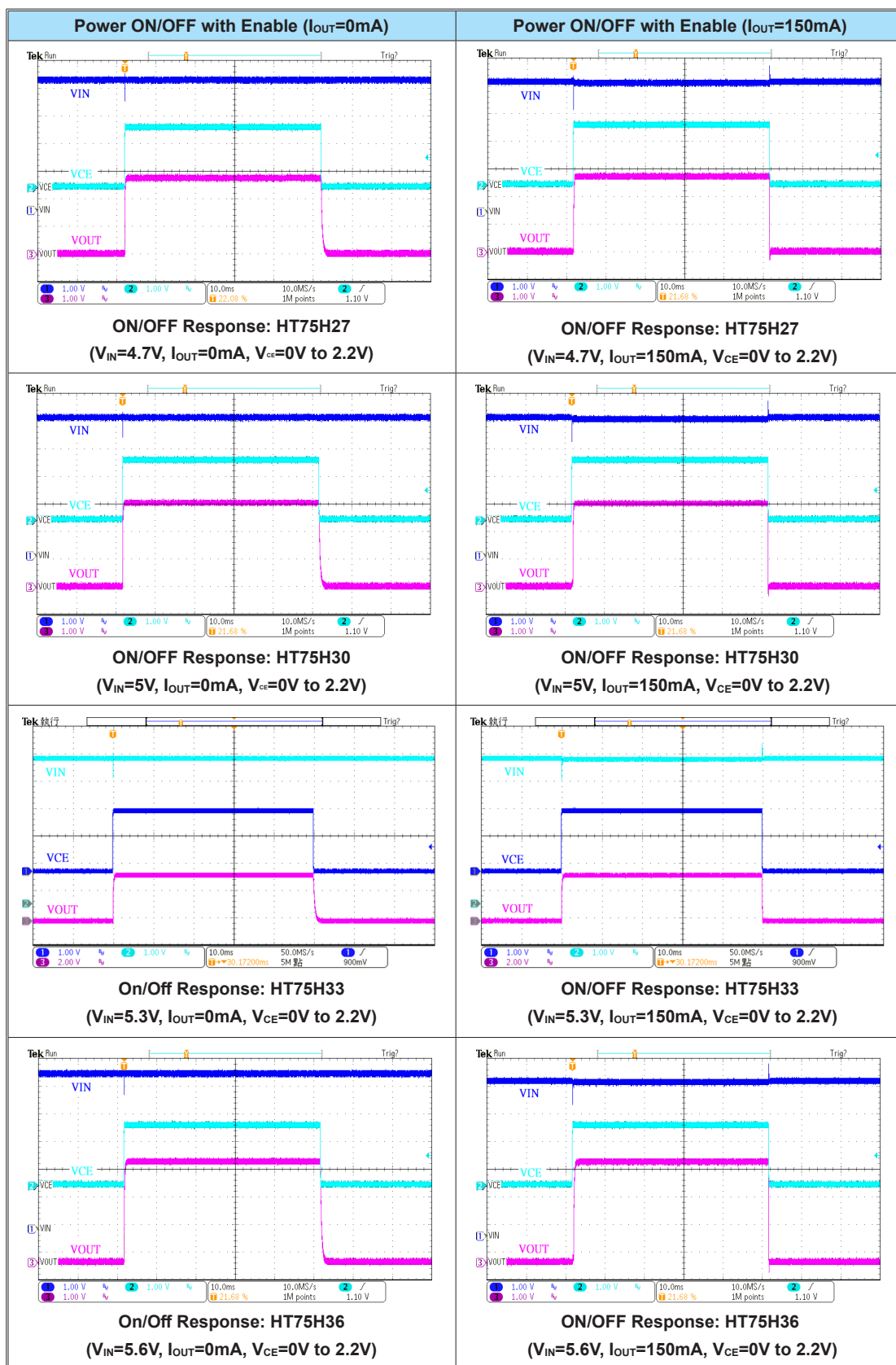


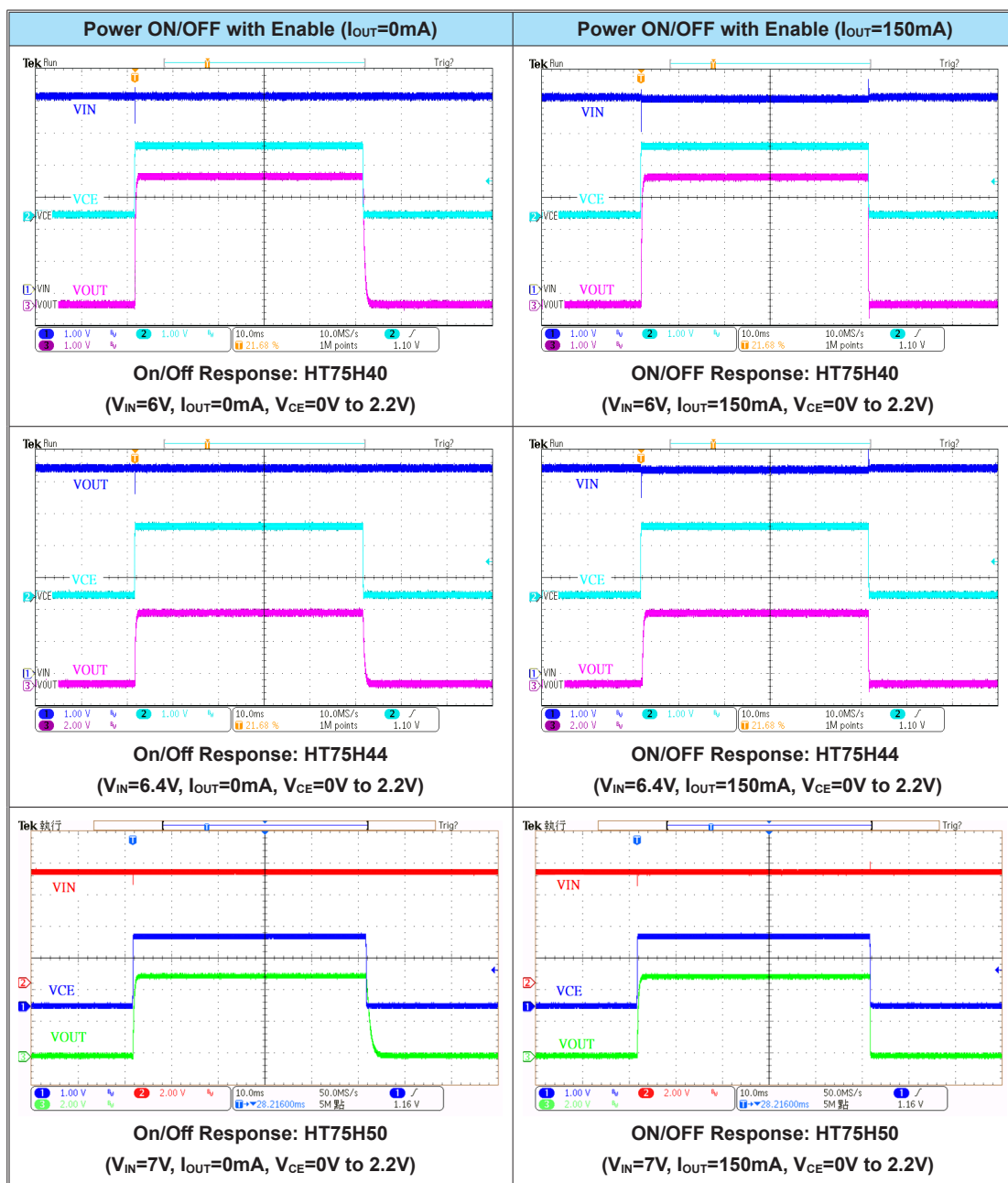




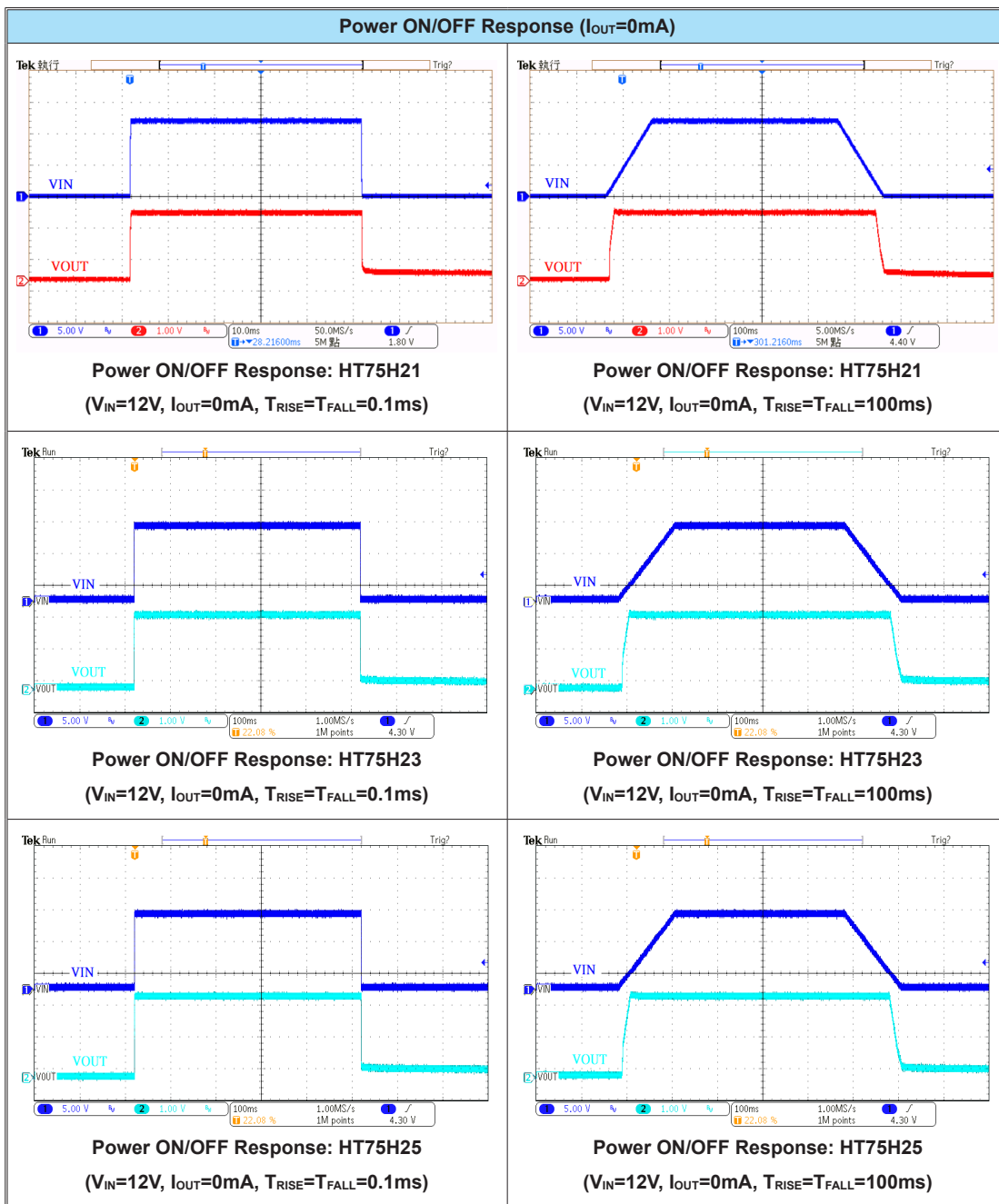
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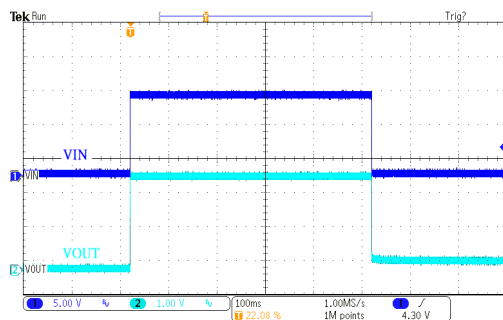




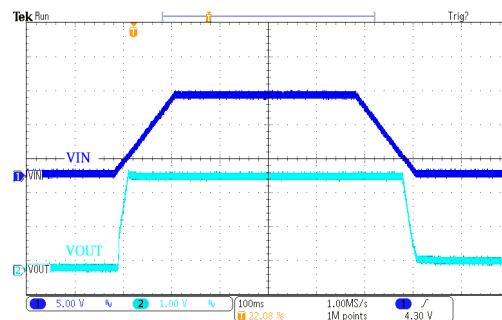
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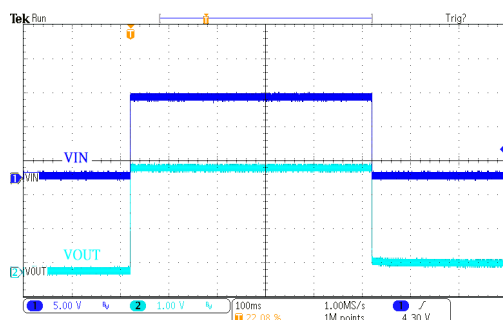
Power ON/OFF Response ($I_{OUT}=0mA$)



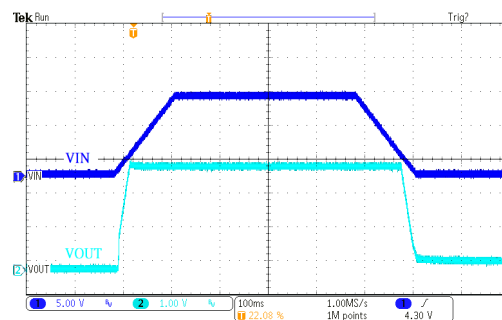
Power ON/OFF Response: HT75H27
($V_{IN}=12V$, $I_{OUT}=0mA$, $T_{RISE}=T_{FALL}=0.1ms$)



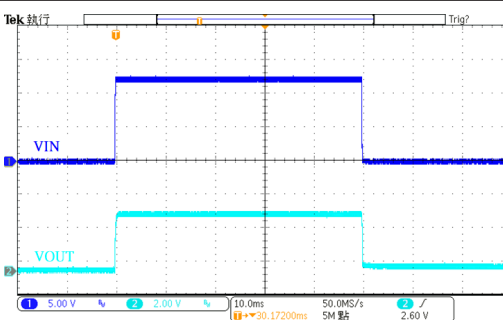
Power ON/OFF Response: HT75H27
($V_{IN}=12V$, $I_{OUT}=0mA$, $T_{RISE}=T_{FALL}=100ms$)



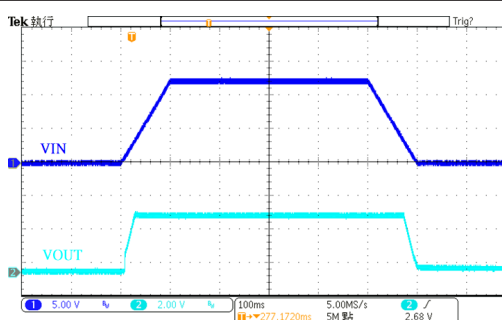
Power ON/OFF Response: HT75H30
($V_{IN}=12V$, $I_{OUT}=0mA$, $T_{RISE}=T_{FALL}=0.1ms$)



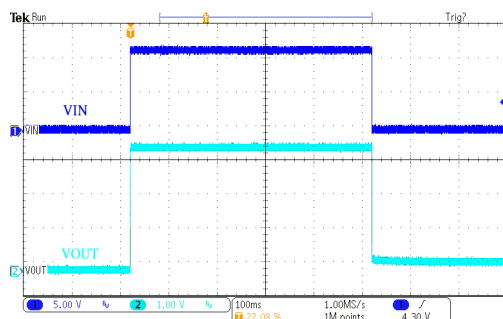
Power ON/OFF Response: HT75H30
($V_{IN}=12V$, $I_{OUT}=0mA$, $T_{RISE}=T_{FALL}=100ms$)



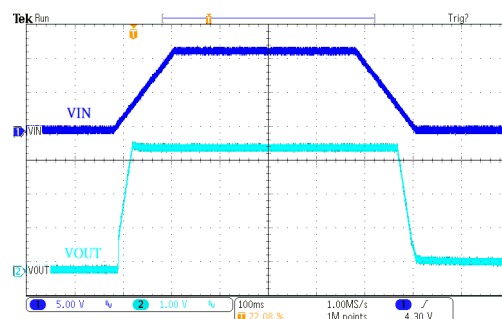
Power ON/OFF Response: HT75H33
($V_{IN}=12V$, $I_{OUT}=0mA$, $T_{RISE}=T_{FALL}=0.1ms$)



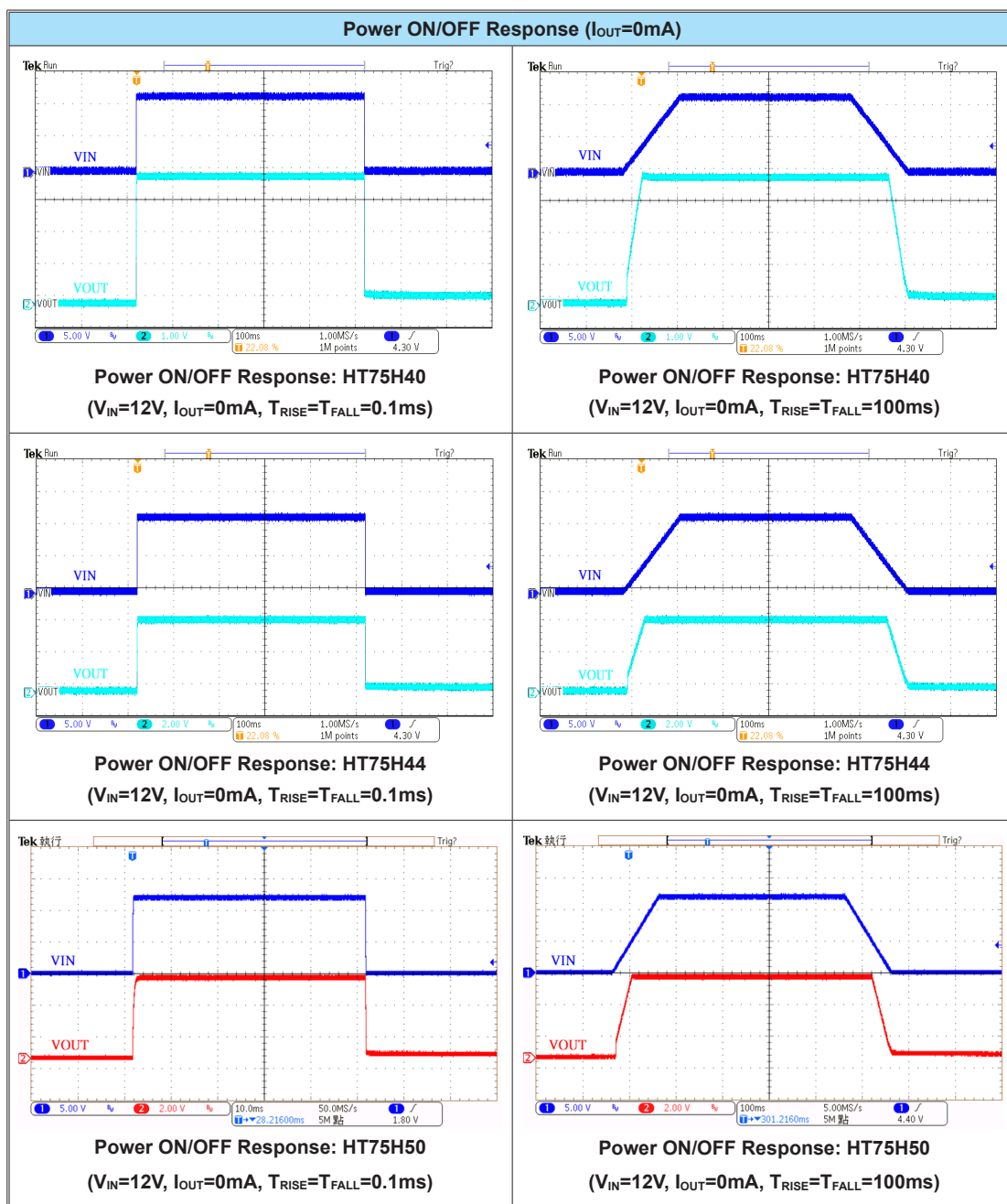
Power ON/OFF Response: HT75H33
($V_{IN}=12V$, $I_{OUT}=0mA$, $T_{RISE}=T_{FALL}=100ms$)



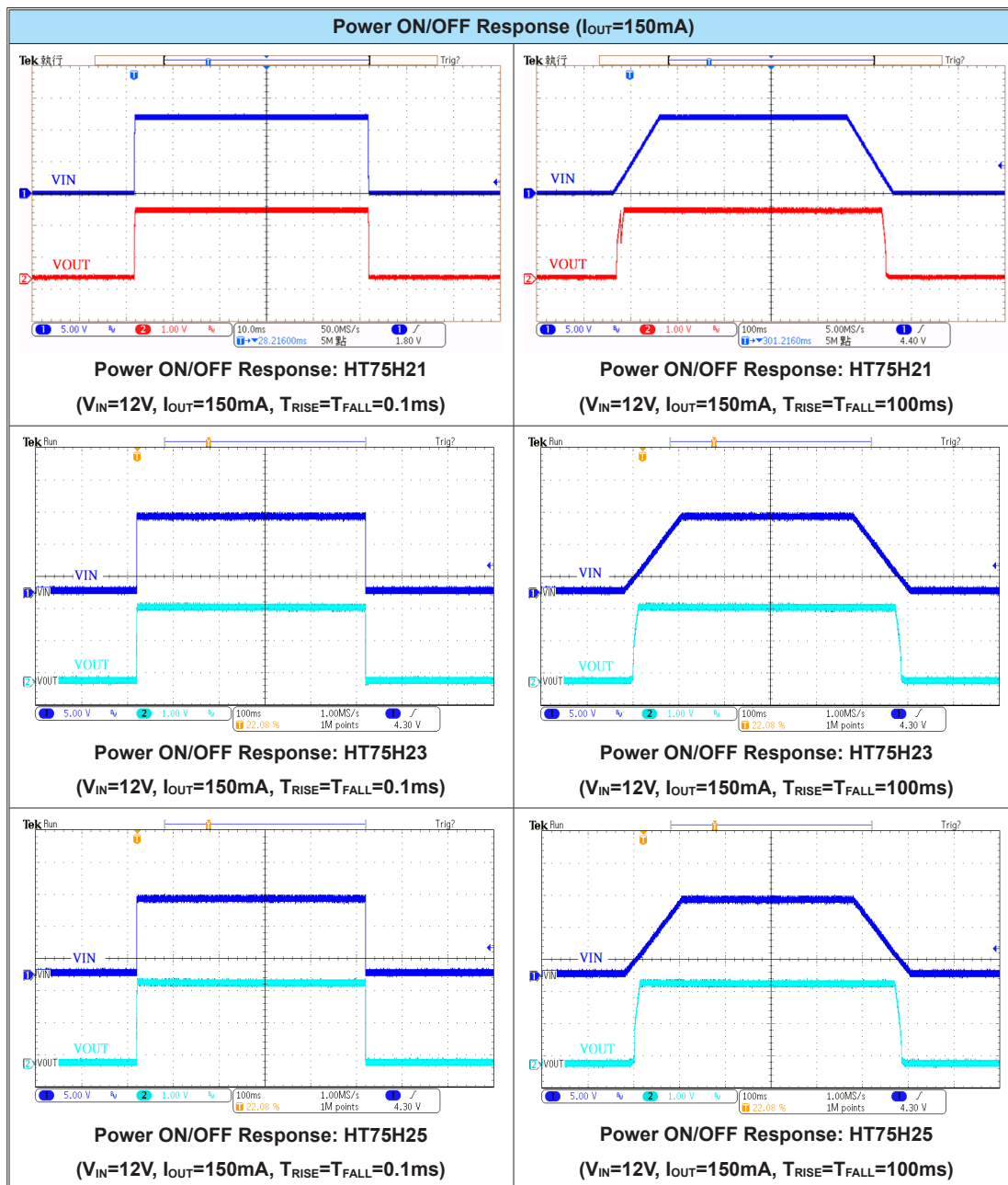
Power ON/OFF Response: HT75H36
($V_{IN}=12V$, $I_{OUT}=0mA$, $T_{RISE}=T_{FALL}=0.1ms$)

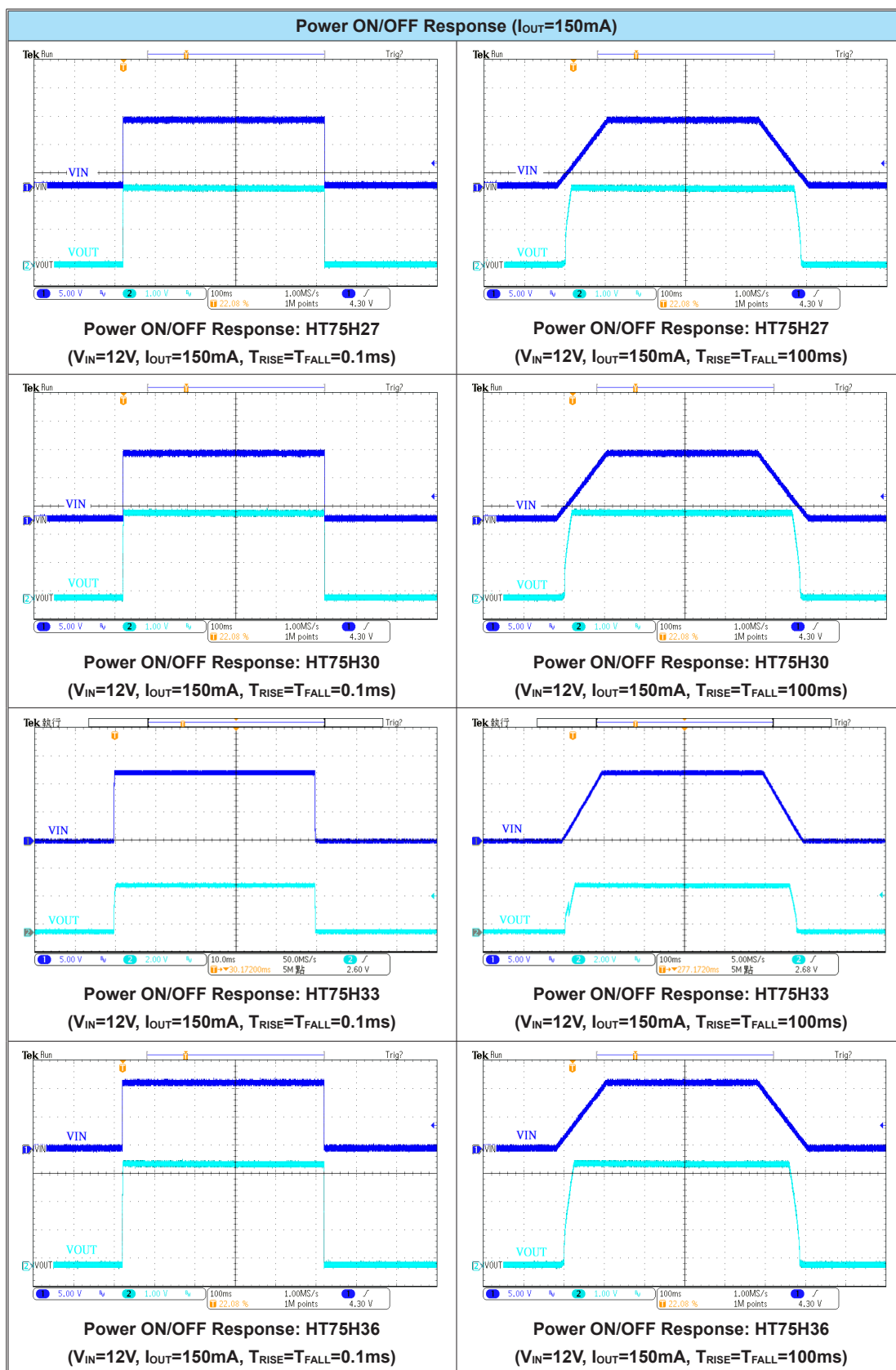


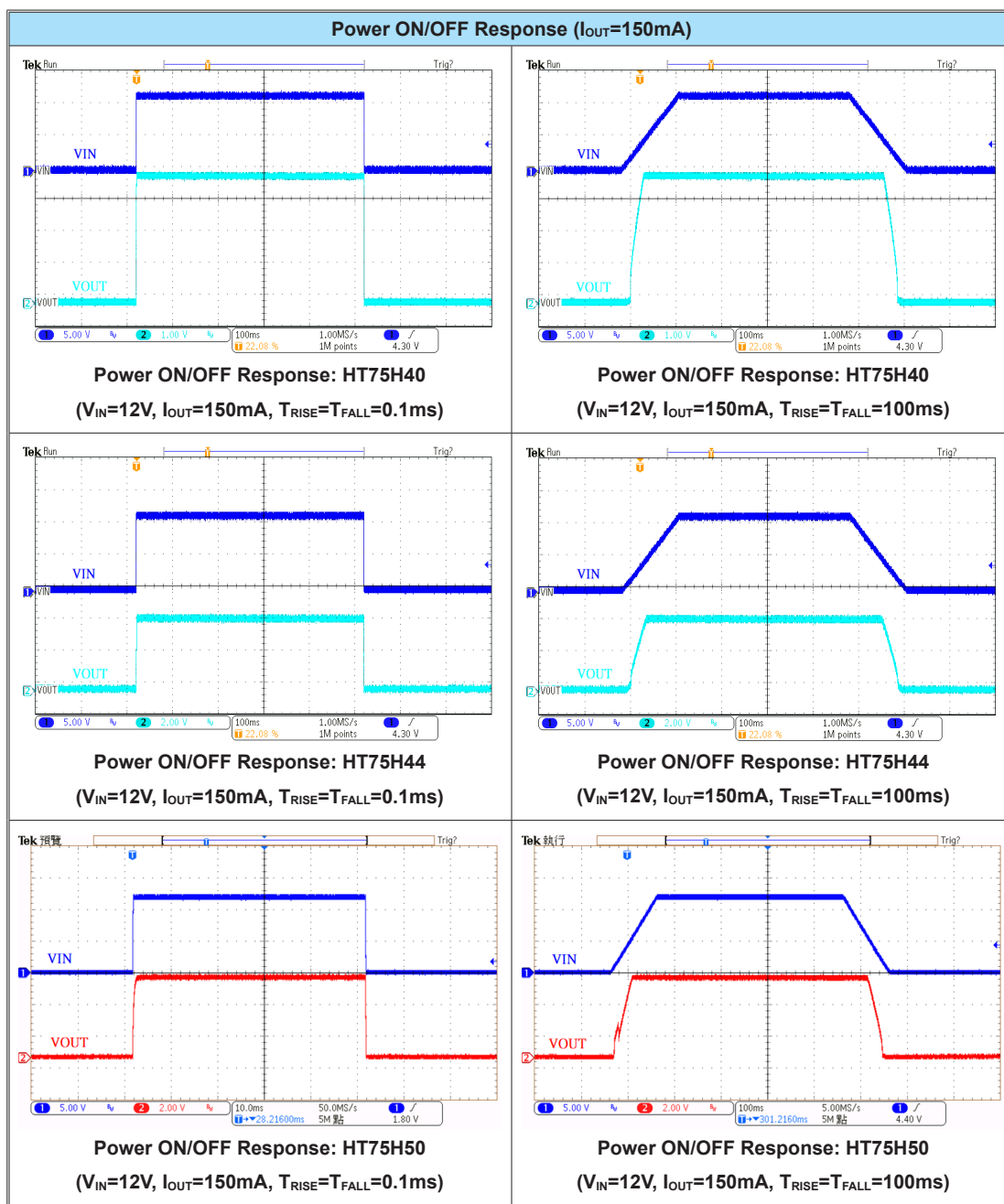
Power ON/OFF Response: HT75H36
($V_{IN}=12V$, $I_{OUT}=0mA$, $T_{RISE}=T_{FALL}=100ms$)



Test Condition: $V_{IN}=V_{OUT}+2V$, $V_{CE}=V_{IN}$, $I_{OUT}=10mA$, $C_{IN}=1\mu F$, $C_{OUT}=1\mu F$ and $T_a=25^{\circ}C$, unless otherwise noted.





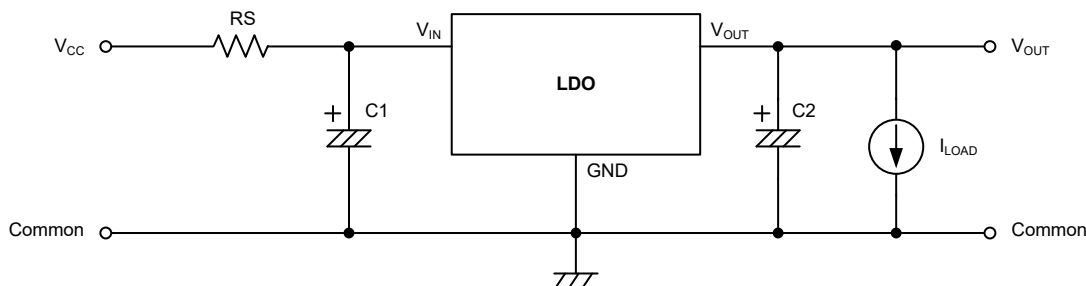


Application Information

When using the HT75Hxx regulators, it is important that the following application points are noted if correct operation is to be achieved.

Power-on Considerations

In order to suppress the output overshooting phenomenon, the rising time of input supply is suggested greater than 1ms. Adding an input resistor R_S which is acting like a low-pass filter, it can slow down the rising time of the input supply in the V_{IN} terminal, as shown below.



The maximum R_S is limited by $I_{LOAD(MAX)}$ and $V_{DROPOUT}$. It be calculated by the following equation.

$$R_S \leq \frac{V_{CC} - V_{DROPOUT}}{I_{LOAD(MAX)}}$$

Once the R_S value is selected, the minimum value of C_1 can be calculated by the following equation:

$$C_1 \geq \frac{1ms}{2.2R_S}$$

OCP and OTP Protections

The HT75Hxx implements the over current protection and over junction temperature protection to prevent IC damage even if the output is shorted to ground. When the output is shorted to ground, the output current will be clamped to I_{OCP2} and the junction temperature will rise. Once the junction temperature exceeds 150°C, the HT75Hxx will shut down the power component to prevent thermal damage. The protection will be released when the junction temperature falls to 120°C.

There are 2 levels of over current protection threshold existing in the HT75Hxx. Once the output voltage is greater than 0.7V, the OCP limit current is set to I_{OCP1} . Otherwise then the output voltage is less than 0.7V, the OCP current folds back to I_{OCP2} in order to slow down the junction temperature rises even if the output terminal is shorted to ground.

Fast Output Discharging Function

When $CE=L$, the output voltage will be fast discharged to 0V via an internal 300Ω resistor. This discharging path doesn't use protections such as OCP/OTP.

Input Capacitor C_{IN} Consideration

It is recommended that the input capacitor be at least 1μF and be ceramic type for better temperature coefficient and lower ESR (Equivalent Series Resistance).

Output Capacitor C_{OUT} Considerations

The output capacitance plays an important role in keeping the output voltage stable. For the ceramic type capacitor, the capacitance should be at least 1μF. For the E-cap type capacitor, the capacitance should be at least 2.2μF.

Thermal Considerations

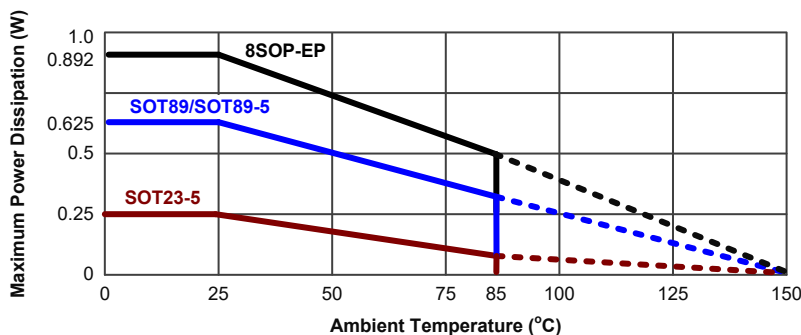
The maximum power dissipation depends on the thermal resistance of the package, the PCB layout, the rate of the surrounding airflow and the difference between the junction and ambient temperature. The maximum power dissipation can be calculated using the following formula:

$$P_{D(MAX)} = (T_{J(MAX)} - T_a) / \theta_{JA}$$

where $T_{J(MAX)}$ is the maximum junction temperature, T_a is the ambient temperature and θ_{JA} is the junction-to-ambient thermal resistance of the IC package in degrees per watt. The following table shows the θ_{JA} values for various package types.

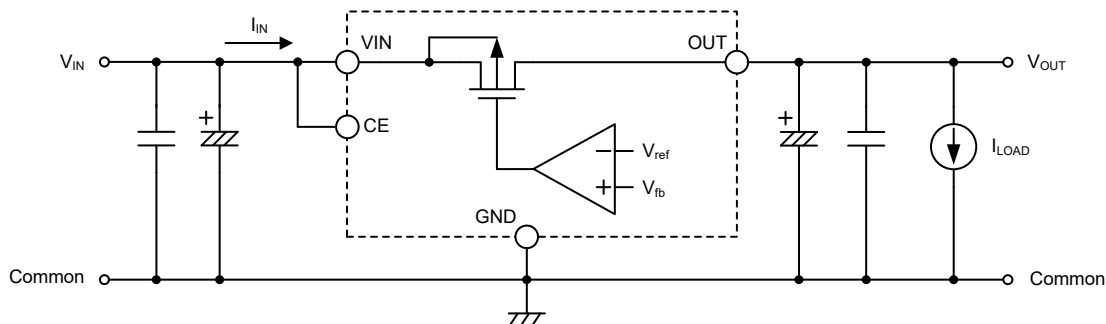
Package Type	θ_{JA} (°C/W)
SOT89	200 °C/W
SOT89-5	200 °C/W
SOT23-5	500 °C/W
8SOP-EP	140 °C/W

For maximum operating rating conditions, the maximum junction temperature is 150°C. However, it is recommended that the maximum junction temperature does not exceed 125°C during normal operation to maintain an adequate margin for device reliability. The derating curves of different packages for maximum power dissipation are as follows:

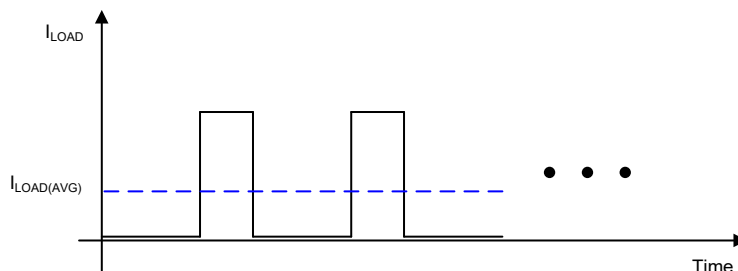


Power Dissipation Calculation

In order to keep the device within its operating limits and to maintain a regulated output voltage, the power dissipation of the device, given by P_D , must not exceed the Maximum Power Dissipation, given by $P_{D(MAX)}$. Therefore, $P_D \leq P_{D(MAX)}$. From the diagram it can be seen that almost all of this power is generated across the pass transistor which is acting like a variable resistor in series with the load to keep the output voltage constant. This generated power which will appear as heat, must never allow the device to exceed its maximum junction temperature.



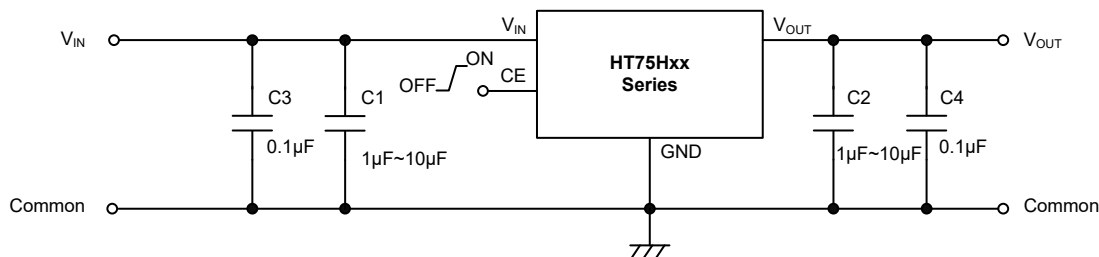
In practical applications the regulator may be called upon to provide both steady state and transient currents due to the transient nature of the load. Although the device may be working well within its limits with its steady state current, care must be taken with transient loads which may cause the current to rise close to its maximum current value. Care must be taken with transient loads and currents as this will result in device junction temperature rises which must not exceed the maximum junction temperature. With both steady state and transient currents, the important current to consider is the average or more precisely the RMS current which is the value of current that will appear as heat generated in the device. The following diagram shows how the average current relates to the transient currents.



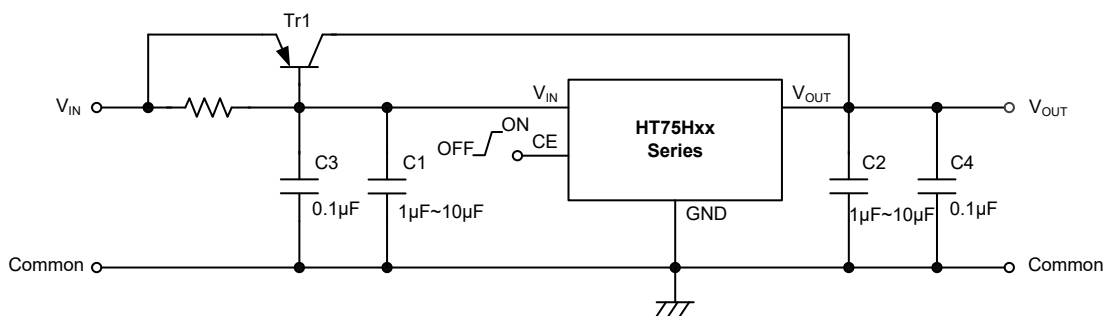
As the quiescent current of the device is very small it can generally be ignored and as a result the input current can be assumed to be equal to the output current. Therefore the power dissipation of the device, P_D , can be calculated as the voltage drop across the input and output multiplied by the current, given by the equation, $P_D = (V_{IN} - V_{OUT}) \times I_{IN}$. As the input current is also equal to the load current the power dissipation $P_D = (V_{IN} - V_{OUT}) \times I_{LOAD}$. However, with transient load currents, $P_D = (V_{IN} - V_{OUT}) \times I_{LOAD(AVG)}$ as shown in the figure.

Application Circuits

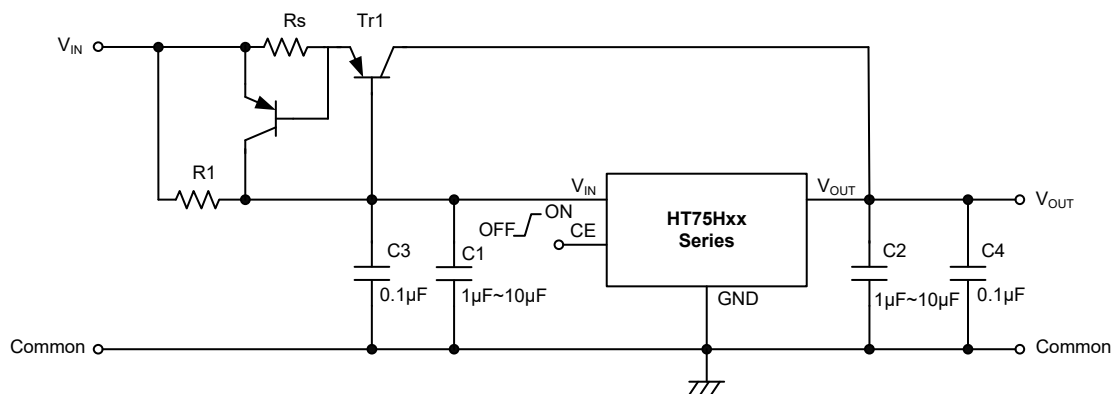
Basic Circuits



High Output Current Positive Voltage Regulator

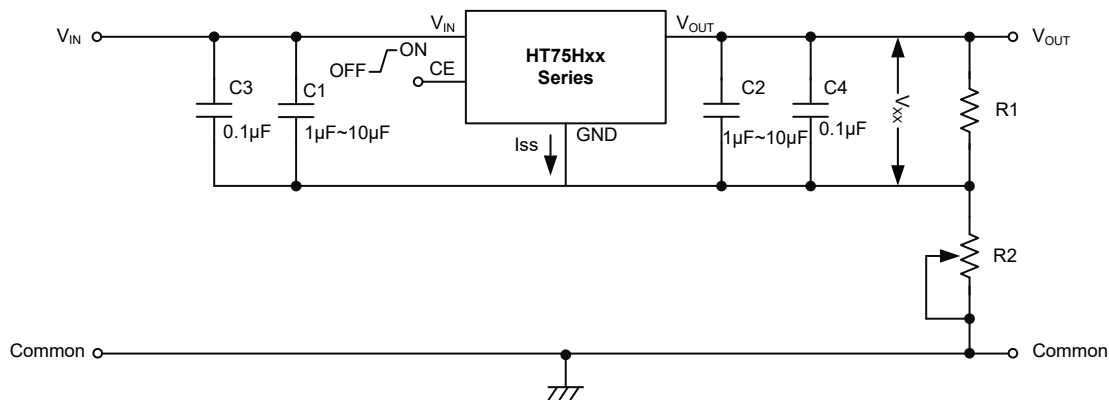


Short-Circuit Protection by Tr1

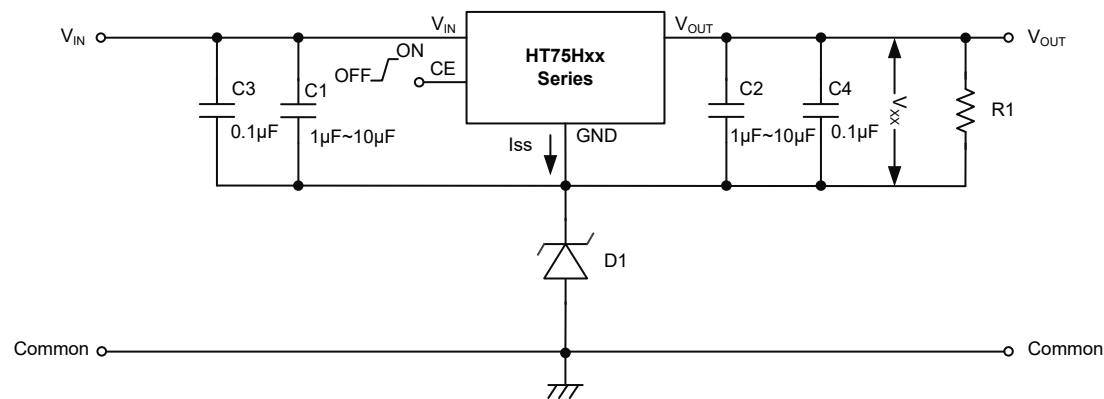


Increasing Output Voltage Circuits

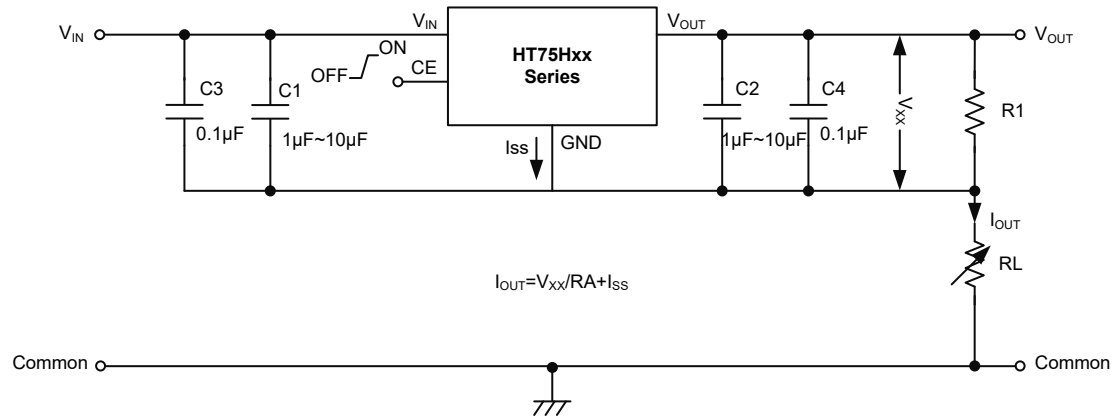
$$V_{OUT} = V_{XX} \times (1 + R2/R1) + I_{SS} \times R2$$



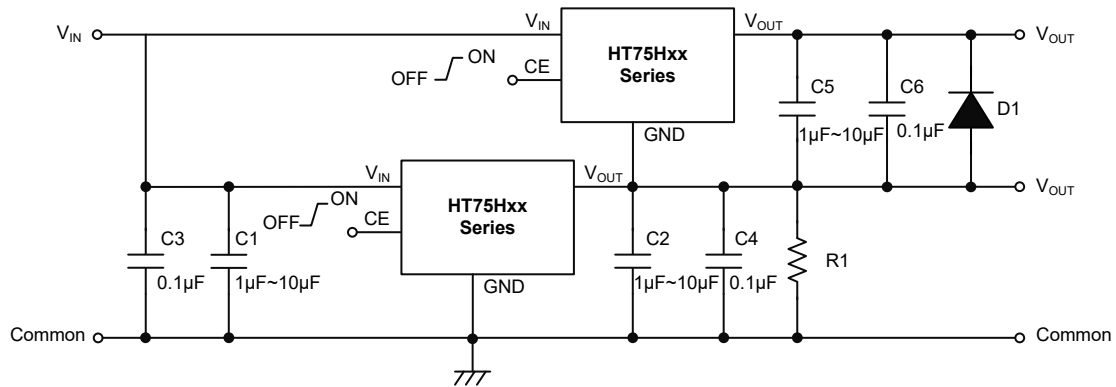
$$V_{OUT} = V_{XX} + V_{D1}$$



Constant Current Regulator



Dual Supply

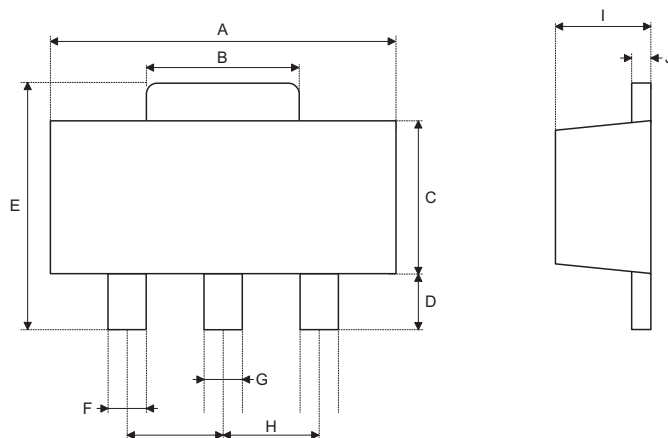


Package Information

Note that the package information provided here is for consultation purposes only. As this information may be updated at regular intervals users are reminded to consult the [Holtek website](#) for the latest version of the [package information](#).

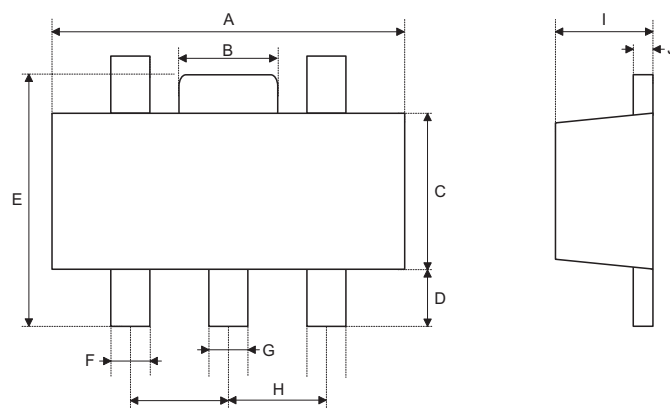
Additional supplementary information with regard to packaging is listed below. Click on the relevant section to be transferred to the relevant website page.

- [Further Package Information \(include Outline Dimensions, Product Tape and Reel Specifications\)](#)
- [Packing Materials Information](#)
- [Carton information](#)

3-pin SOT89 Outline Dimensions


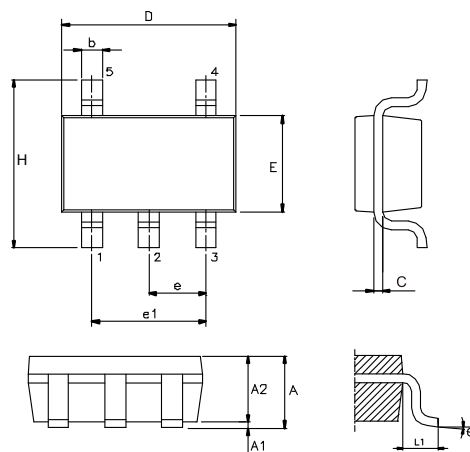
Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	0.173	—	0.185
B	0.053	—	0.072
C	0.090	—	0.106
D	0.031	—	0.047
E	0.155	—	0.173
F	0.014	—	0.019
G	0.017	—	0.022
H	—	0.059 BSC	—
I	0.055	—	0.063
J	0.014	—	0.017

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	4.40	—	4.70
B	1.35	—	1.83
C	2.29	—	2.70
D	0.80	—	1.20
E	3.94	—	4.40
F	0.36	—	0.48
G	0.44	—	0.56
H	—	1.50 BSC	—
I	1.40	—	1.60
J	0.35	—	0.44

5-pin SOT89 Outline Dimensions


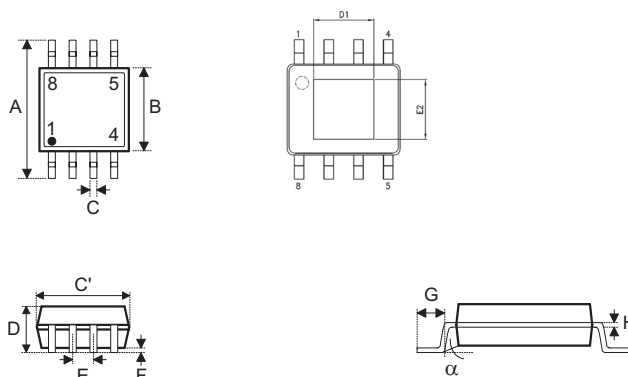
Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	0.173	—	0.181
B	0.055	—	0.071
C	0.091	—	0.102
D	0.035	—	0.043
E	0.155	—	0.167
F	0.014	—	0.022
G	0.013	—	0.020
H	—	0.059 BSC	—
I	0.055	—	0.063
J	0.014	—	0.017

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	4.40	—	4.60
B	1.40	—	1.80
C	2.30	—	2.60
D	0.90	—	1.10
E	3.94	—	4.25
F	0.36	—	0.56
G	0.32	—	0.52
H	—	1.50 BSC	—
I	1.40	—	1.60
J	0.35	—	0.44

5-pin SOT23 Outline Dimensions


Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	—	—	0.057
A1	—	—	0.006
A2	0.035	0.045	0.051
b	0.012	—	0.020
C	0.003	—	0.009
D	—	0.114 BSC	—
E	—	0.063 BSC	—
e	—	0.037 BSC	—
e1	—	0.075 BSC	—
H	—	0.110 BSC	—
L1	—	0.024 BSC	—
θ	0°	—	8°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	—	—	1.45
A1	—	—	0.15
A2	0.90	1.15	1.30
b	0.30	—	0.50
C	0.08	—	0.22
D	—	2.90 BSC	—
E	—	1.60 BSC	—
e	—	0.95 BSC	—
e1	—	1.90 BSC	—
H	—	2.80 BSC	—
L1	—	0.60 BSC	—
θ	0°	—	8°

8-pin SOP-EP (150mil) Outline Dimensions


Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	—	0.236 BSC	—
B	—	0.154 BSC	—
C	0.012	—	0.020
C'	—	0.193 BSC	—
D	—	—	0.069
D1	0.059	—	—
E	—	0.050 BSC	—
E2	0.039	—	—
F	0.000	—	0.006
G	0.016	—	0.050
H	0.004	—	0.010
α	0°	—	8°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	—	6.00 BSC	—
B	—	3.90 BSC	—
C	0.31	—	0.51
C'	—	4.90 BSC	—
D	—	—	1.75
D1	1.50	—	—
E	—	1.27 BSC	—
E2	1.00	—	—
F	0.00	—	0.15
G	0.40	—	1.27
H	0.10	—	0.25
α	0°	—	8°

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